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(54) **LED DOWNLIGHT**

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(2013.01); **F21V 21/047** (2013.01); **F21V 29/89**
(2015.01); **F21Y 2101/02** (2013.01)

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F21V 29/22; **F21V 29/2206**; **F21V 29/2212**;
F21V 29/246; **F21V 13/02**; **F21V 21/047**;
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F21S 8/02

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362/311.02, **364-365**, **800**

See application file for complete search history.

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Primary Examiner — Jason Moon Han

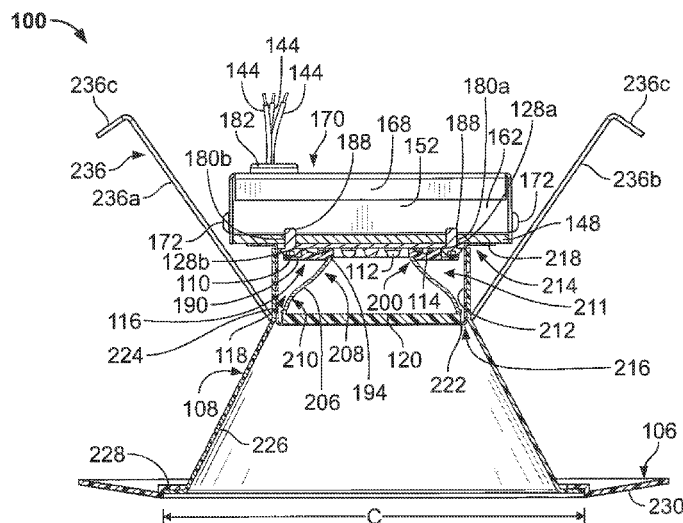
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(57)

ABSTRACT

A lighting device includes a substrate, a light emitting diode (LED) array mounted on a first surface of the substrate, and circuit components mounted on the first surface of the substrate and coupled to the LED array wherein the circuit components are adapted to control electrical power applied to the LED array. A heat exchanger is mounted on a second surface of the substrate and a reflector is disposed about the LED array wherein the reflector has a reflection surface that is convex on a first side of an inflection locus and concave on a second side of the inflection locus, and wherein the first side of the inflection locus is proximate the LED array. A diffuser is adjacent the second side of the inflection locus of the reflector.

42 Claims, 16 Drawing Sheets



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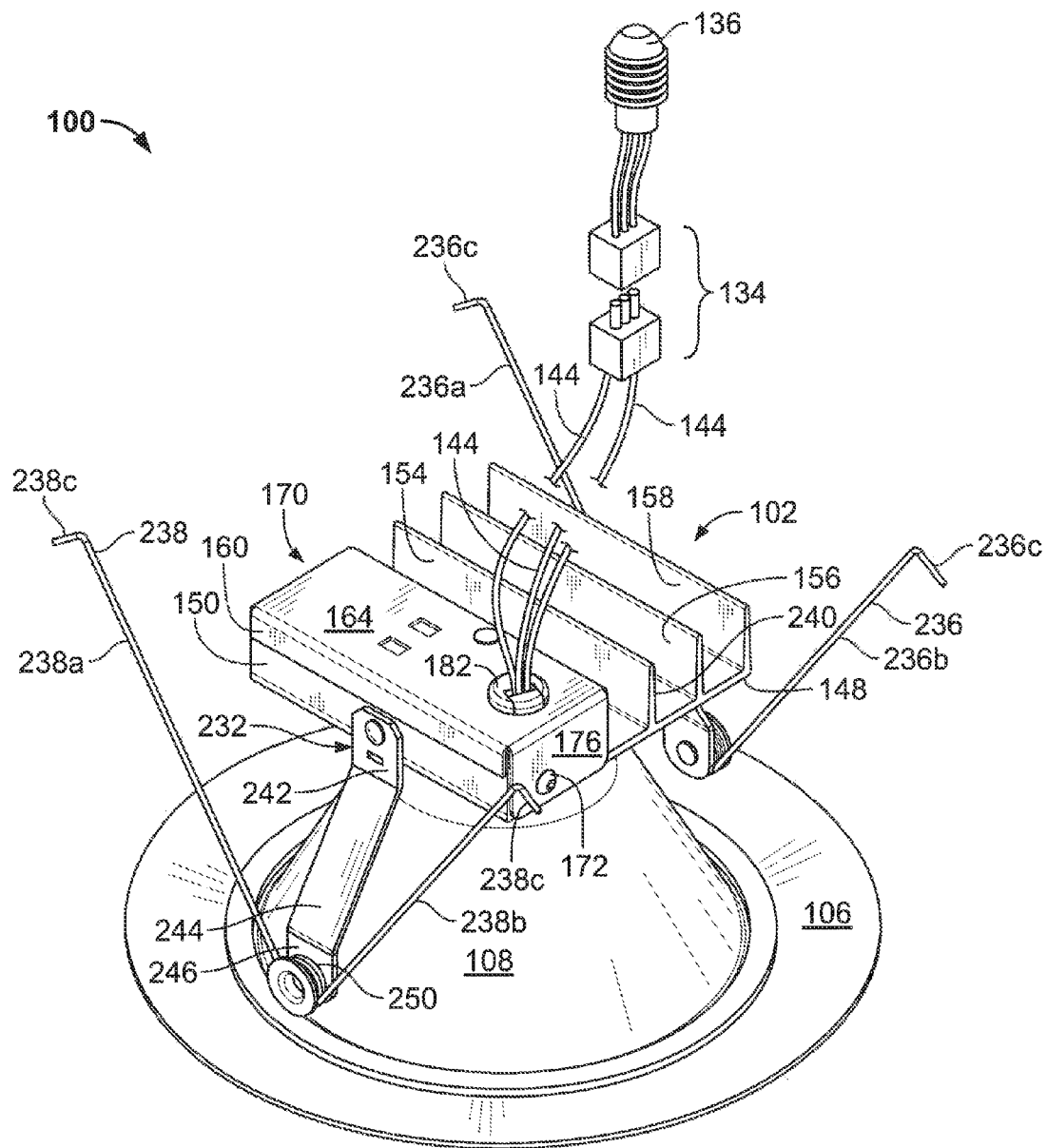
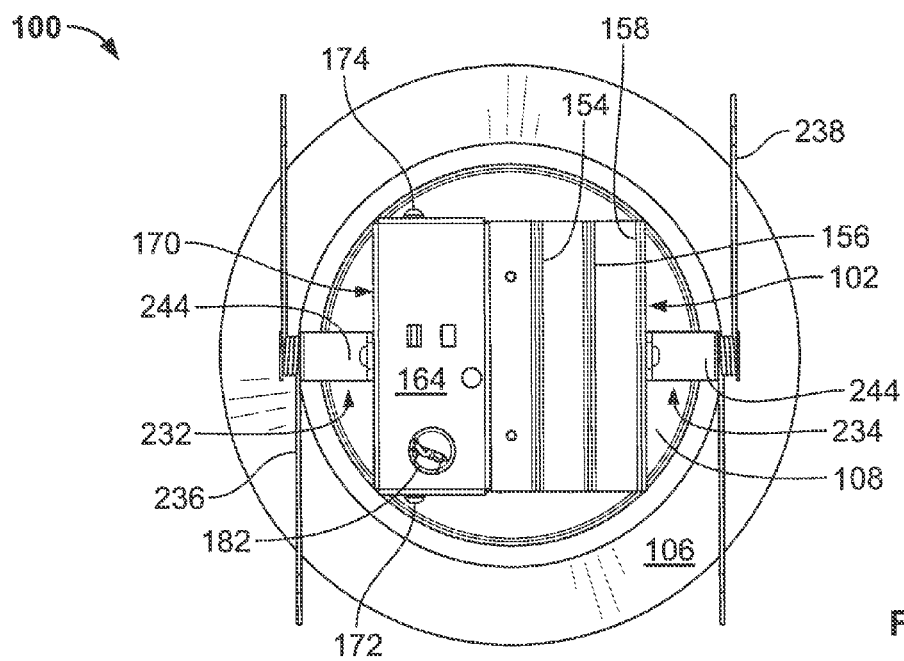
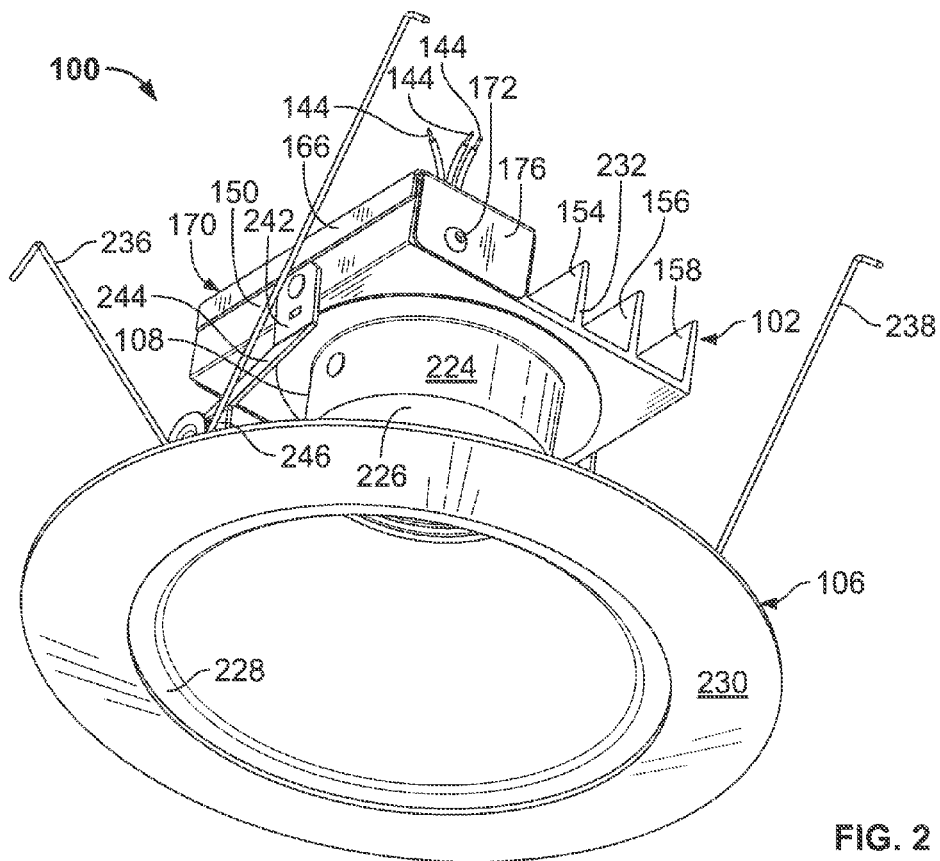


FIG. 1



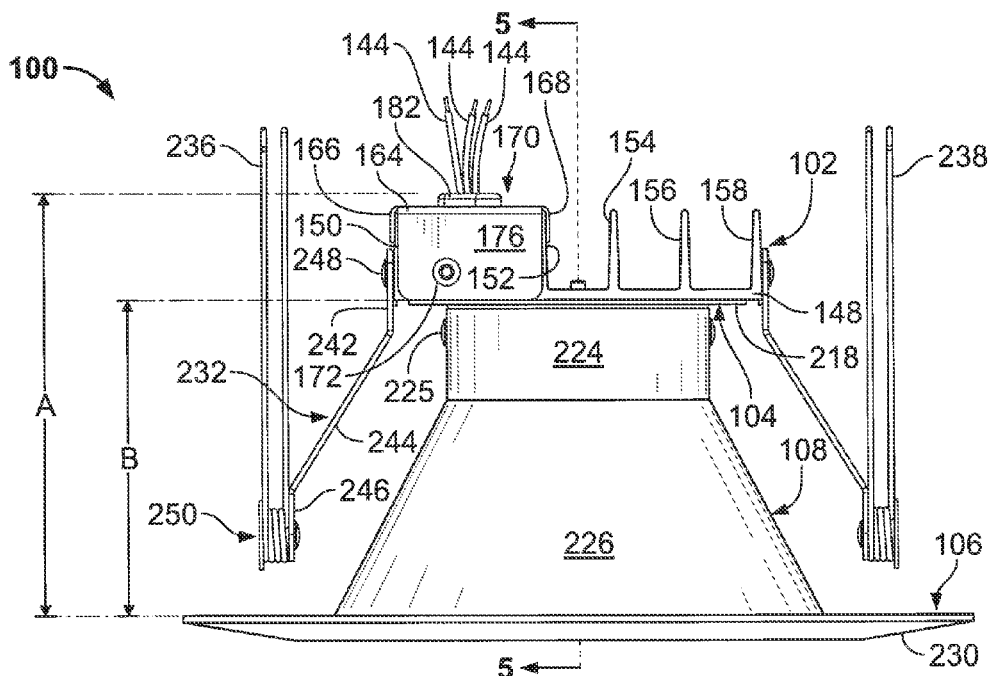


FIG. 4

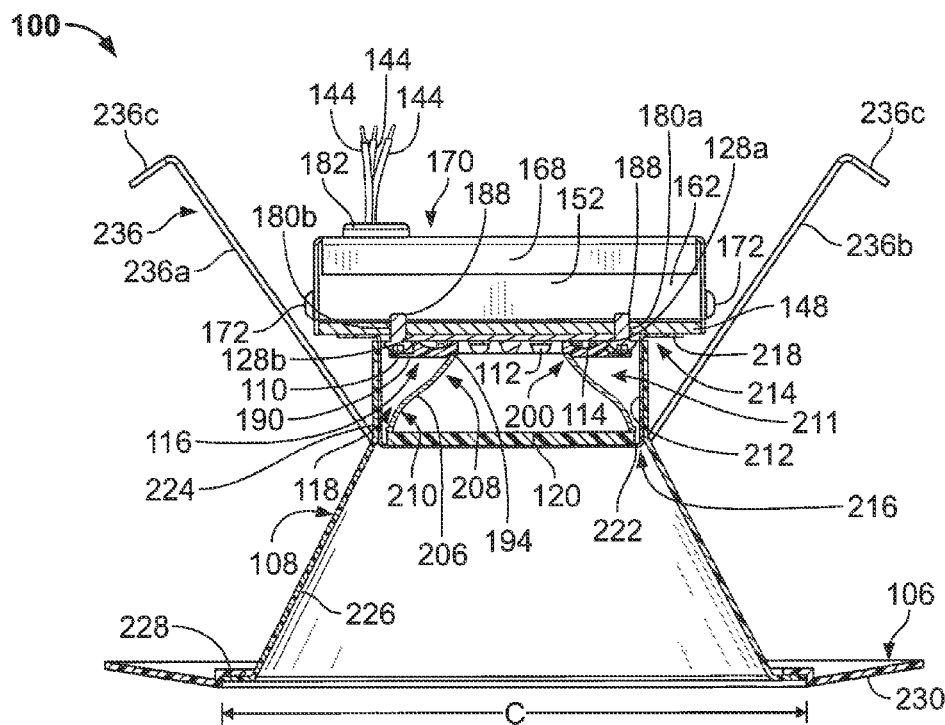


FIG. 5

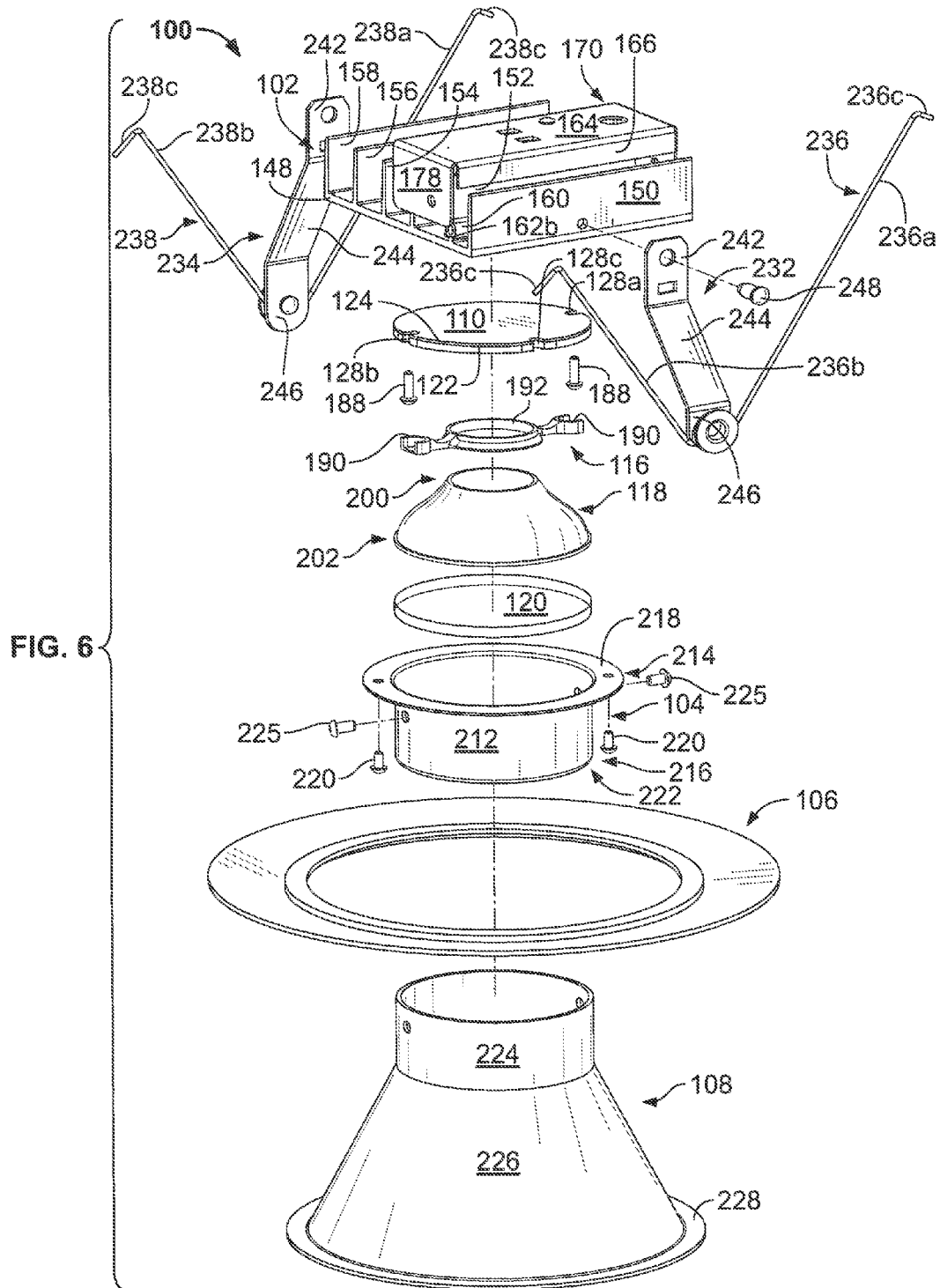
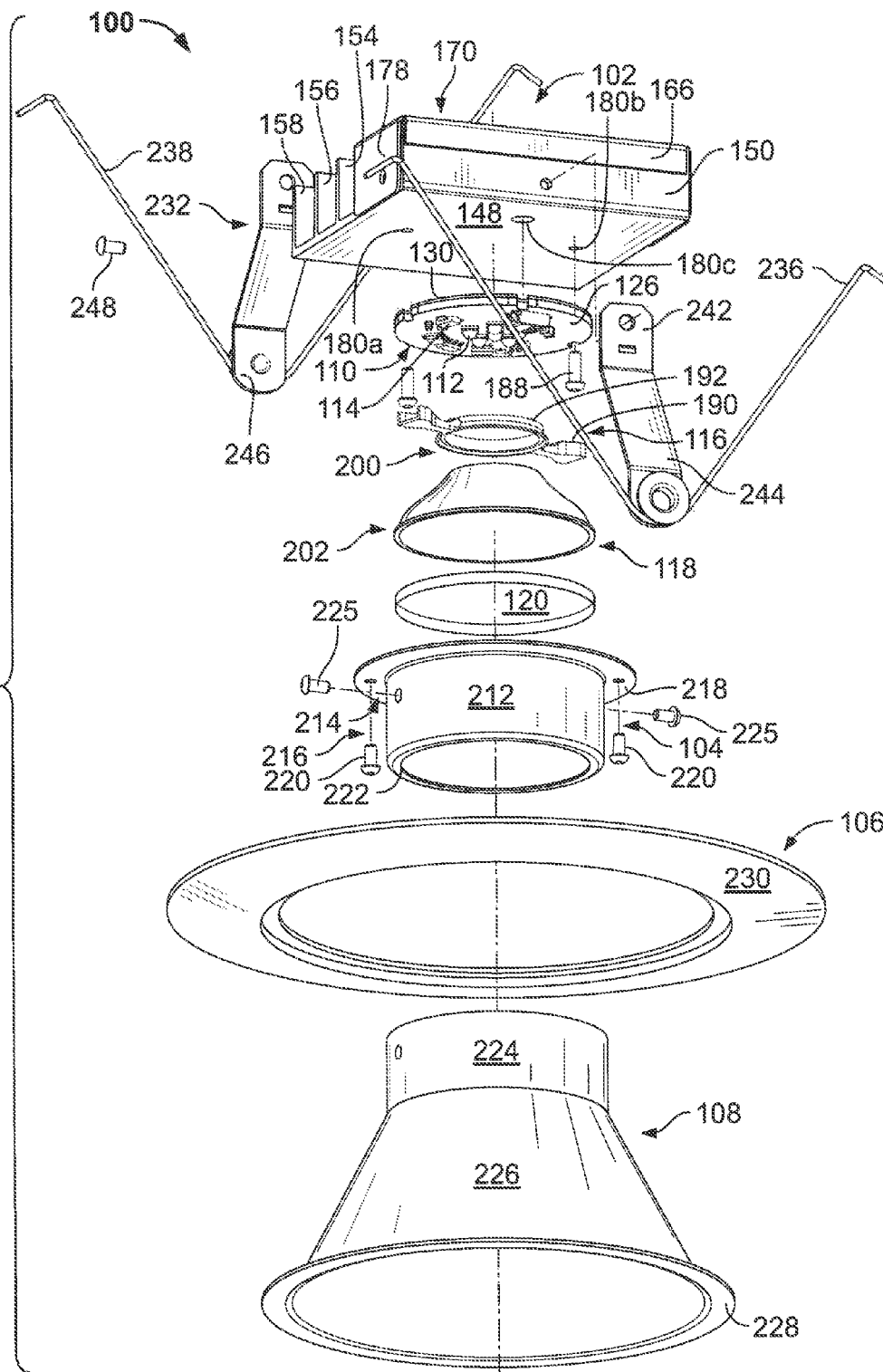


FIG. 7



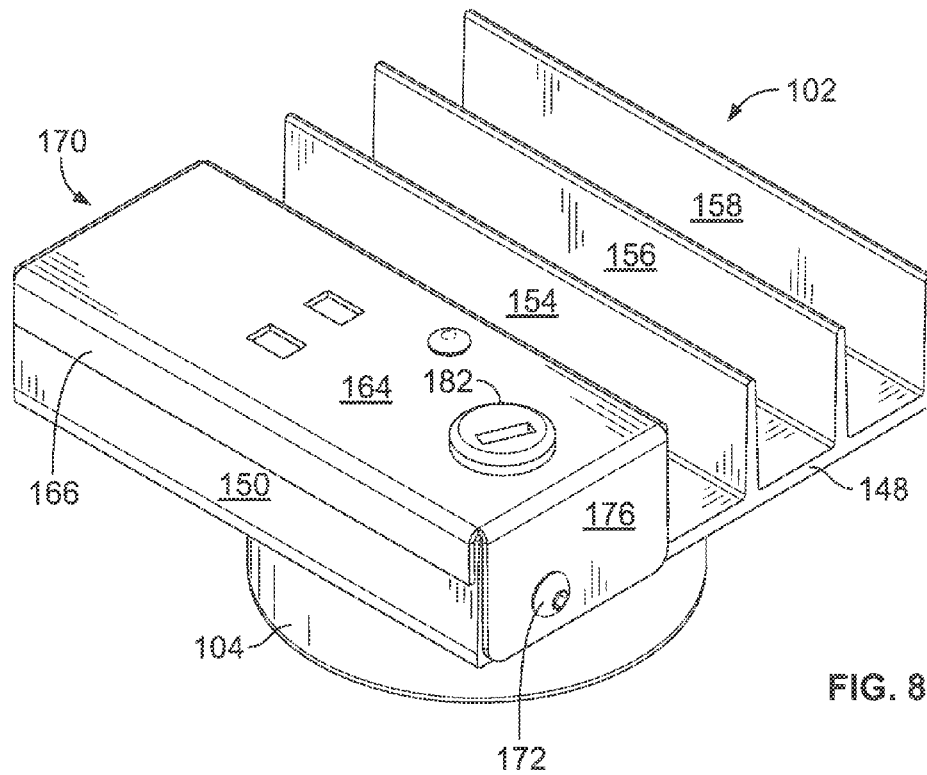


FIG. 8

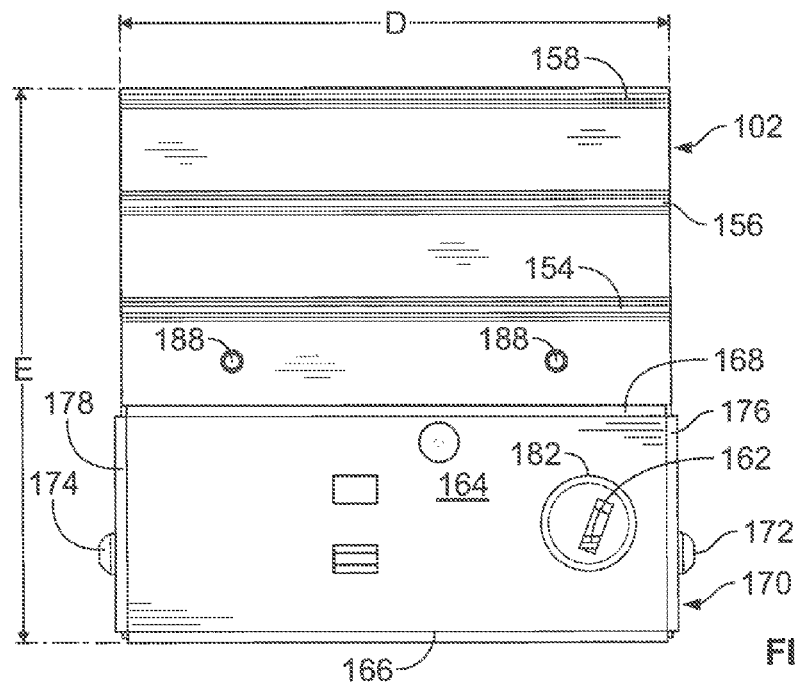


FIG. 9

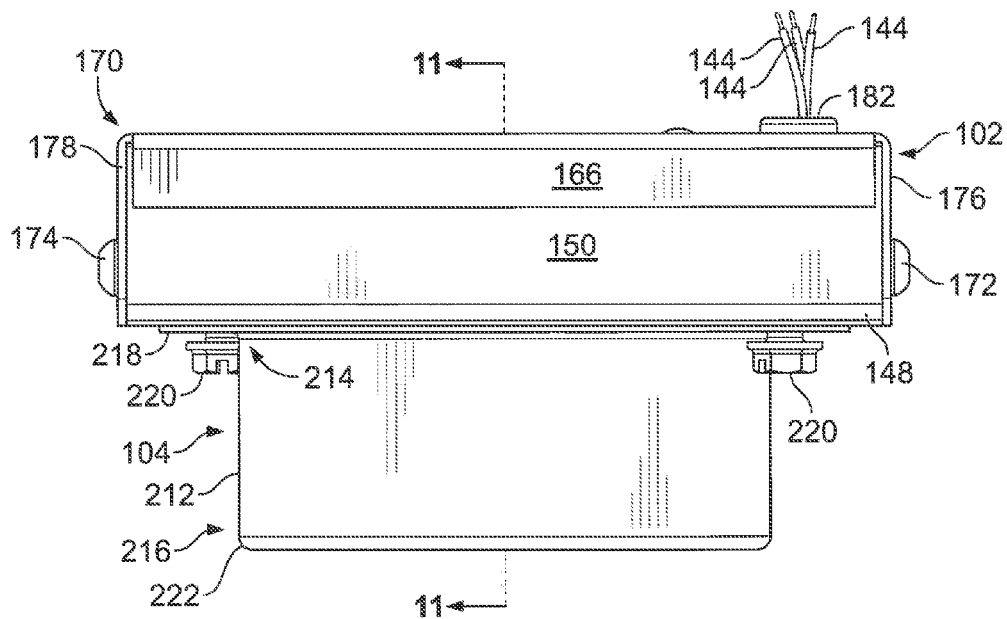


FIG. 10

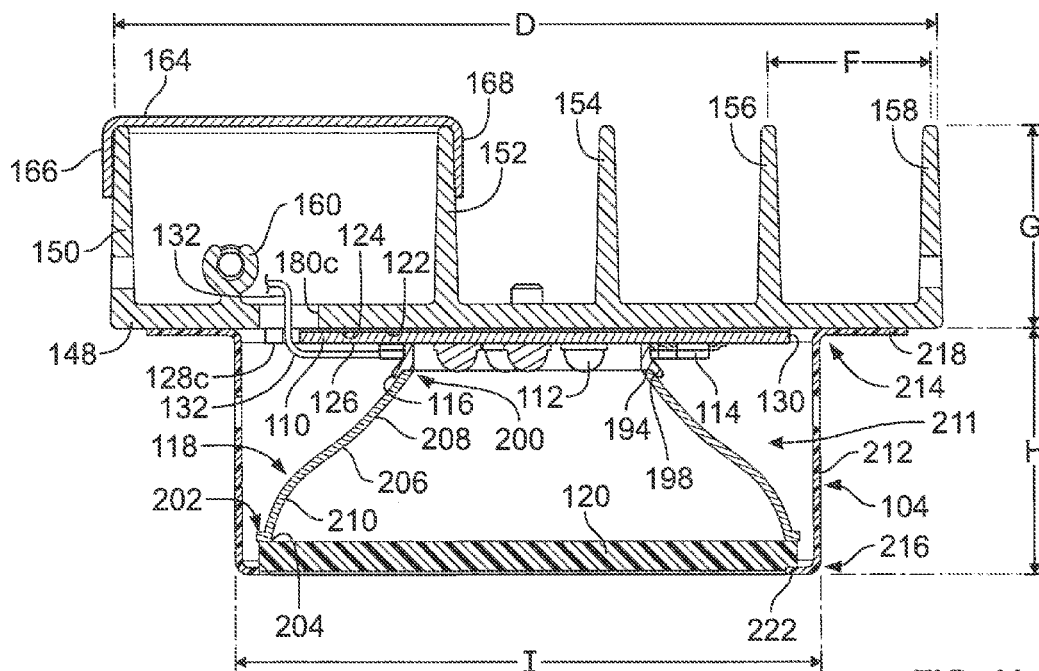


FIG. 11

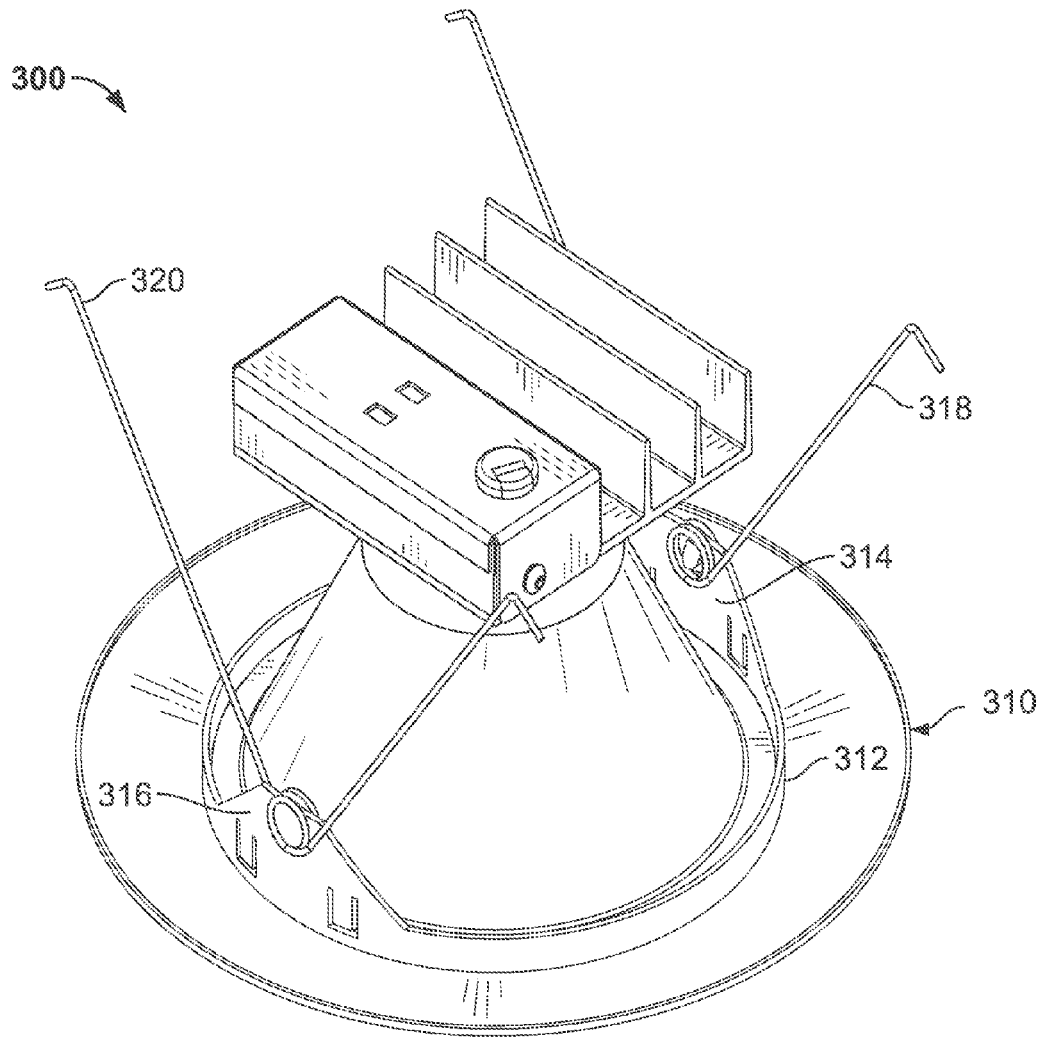


FIG. 12

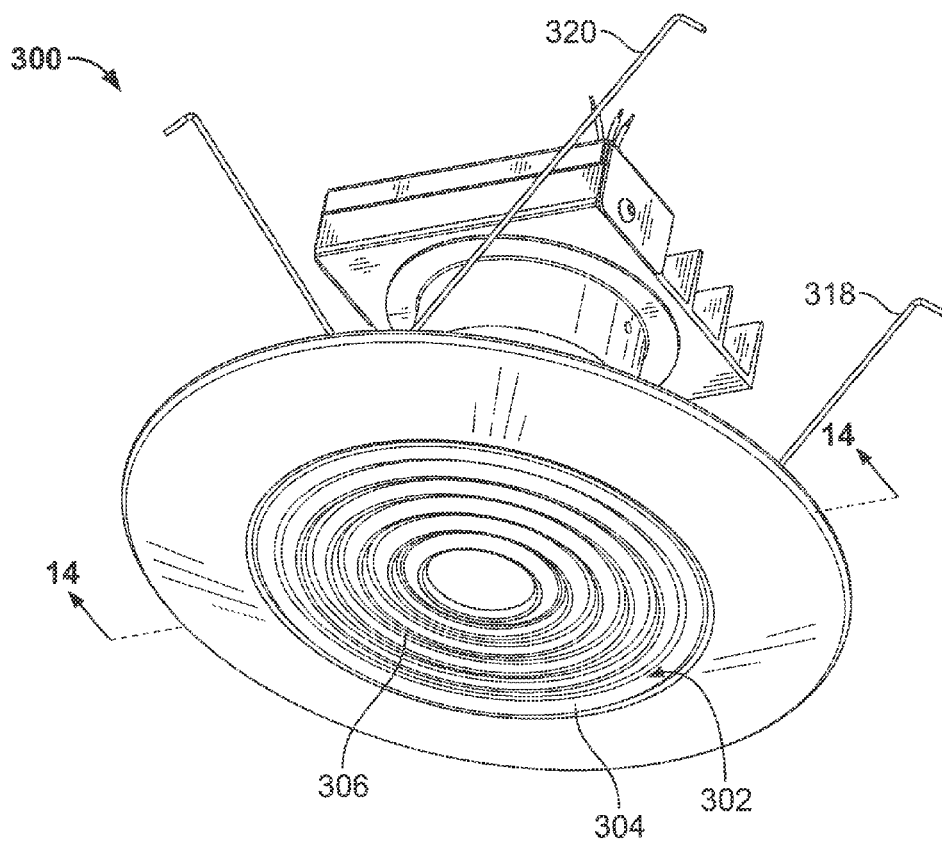


FIG. 13

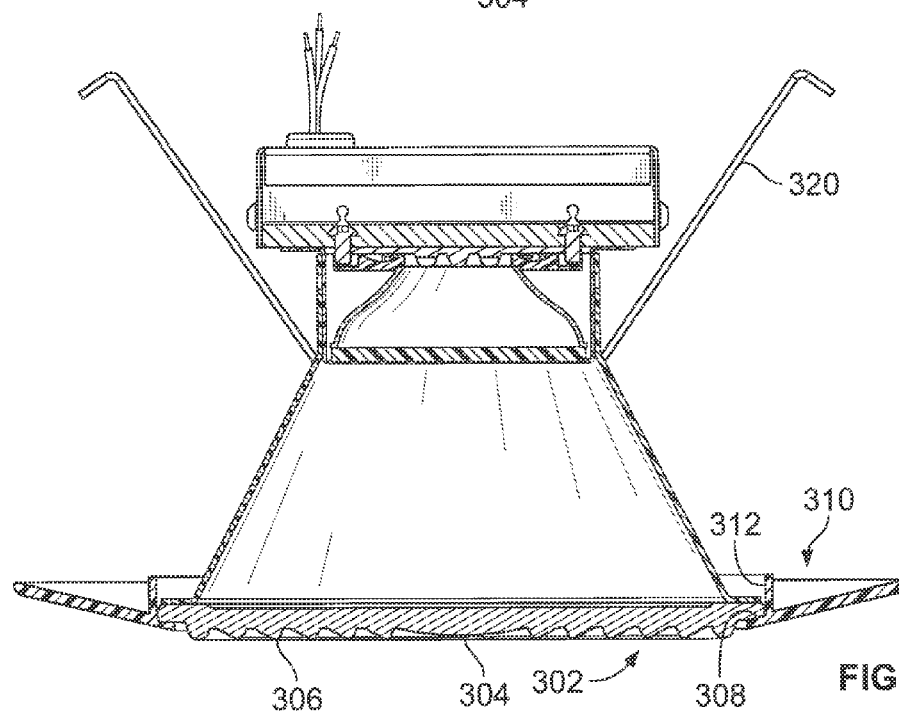
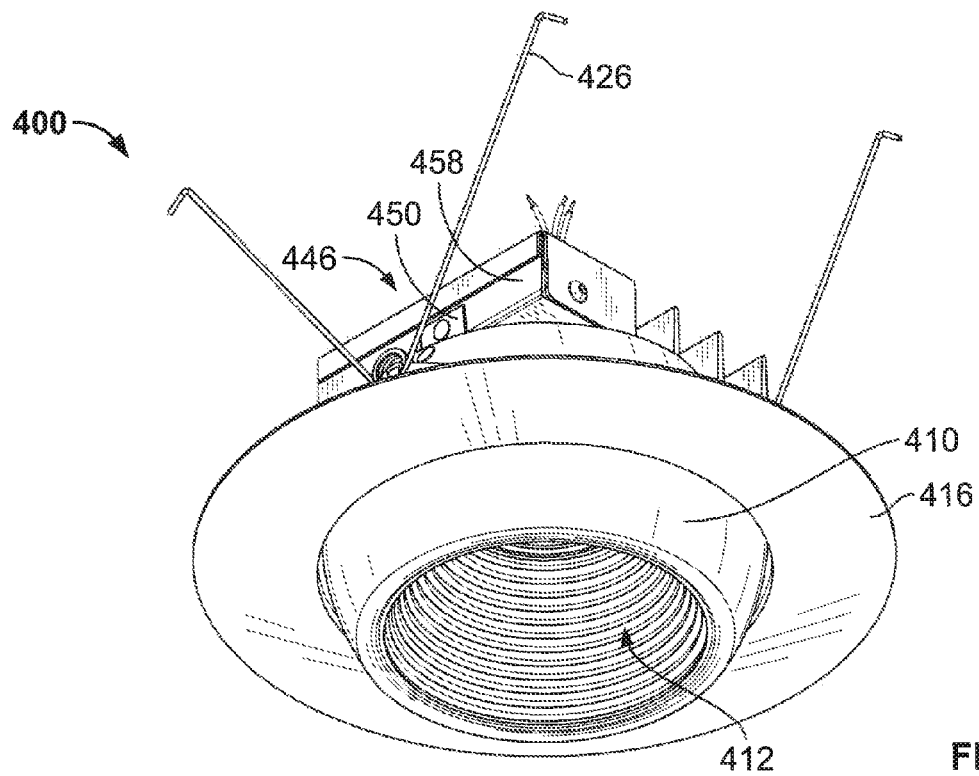
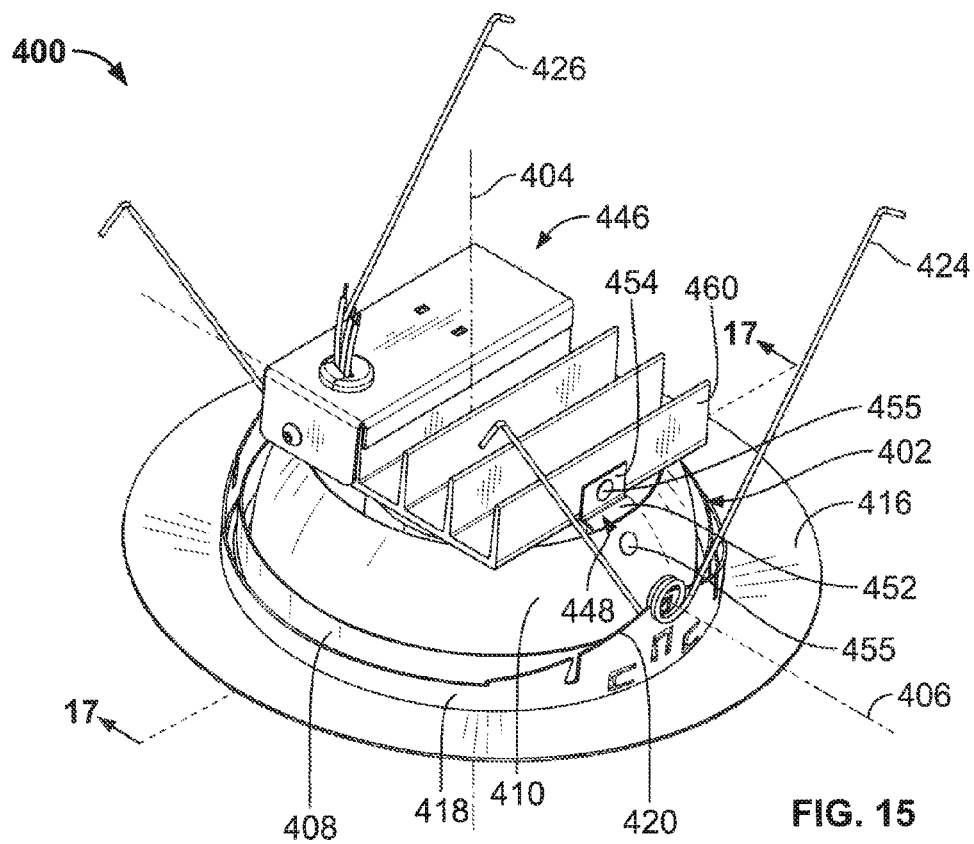


FIG. 14



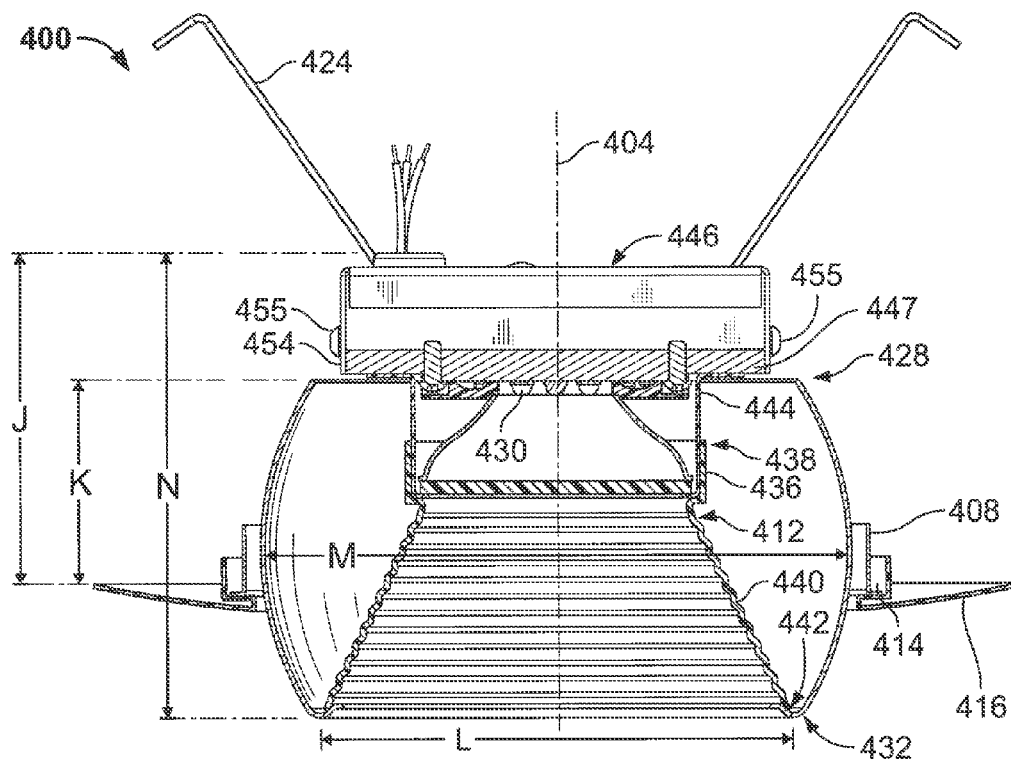


FIG. 17

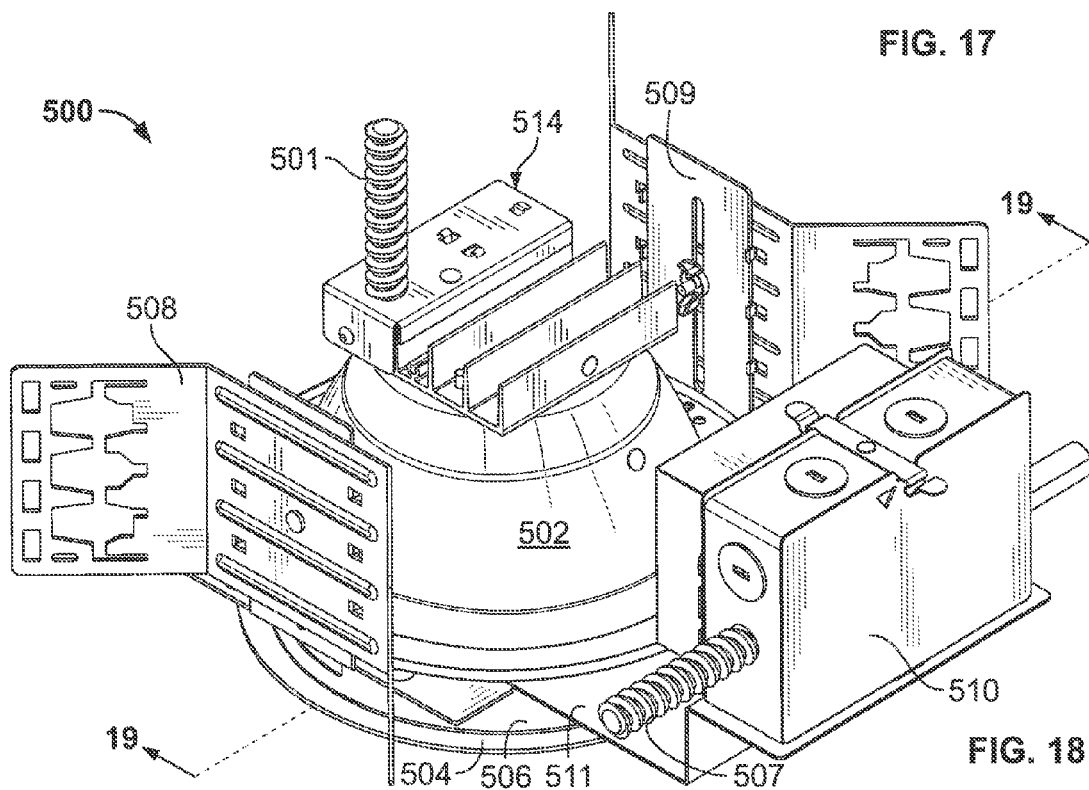
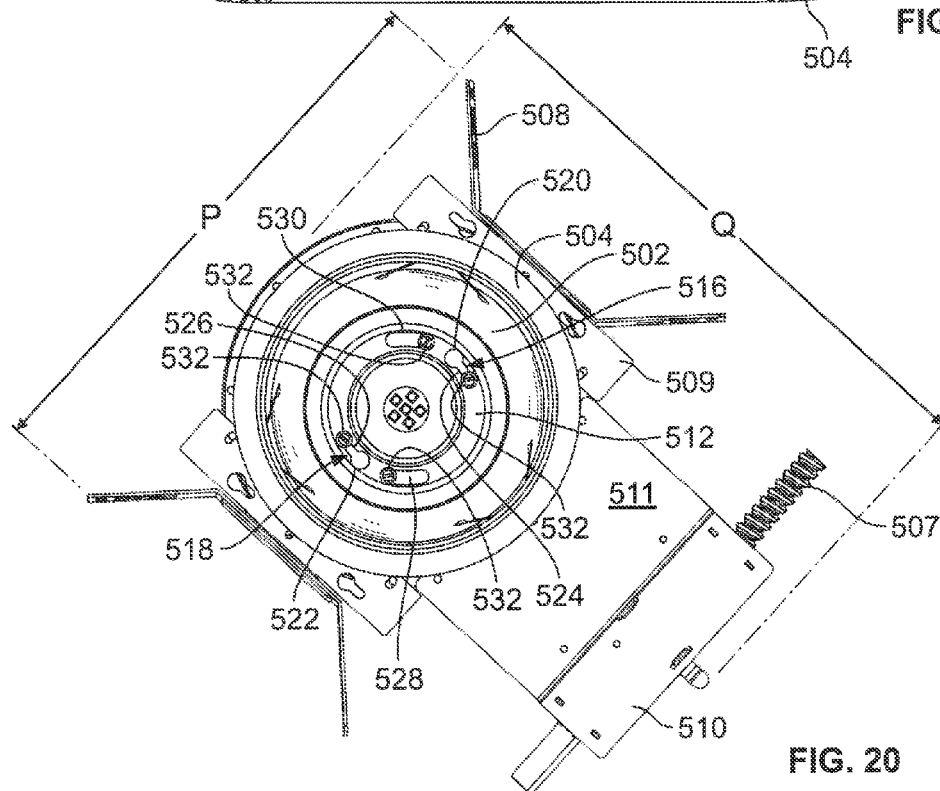
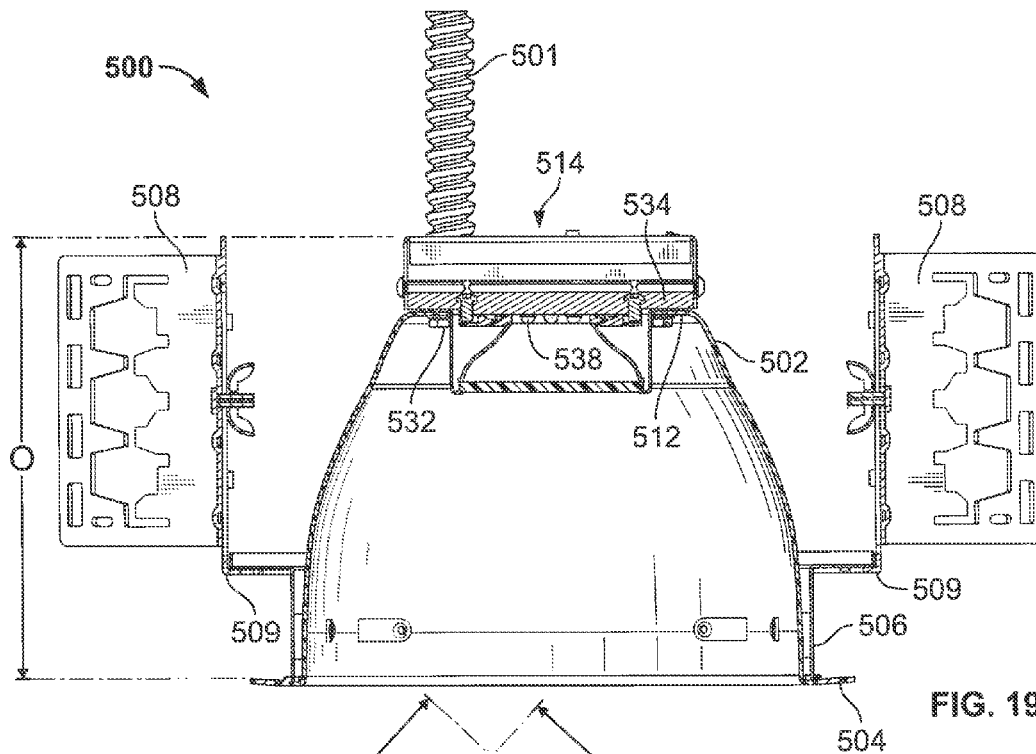


FIG. 18



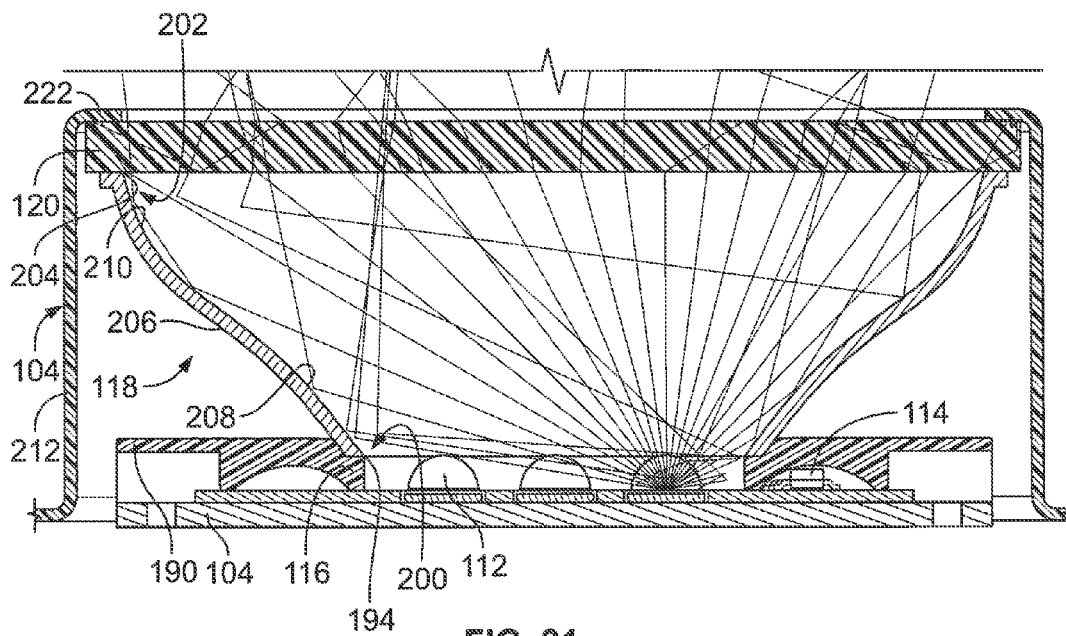


FIG. 21

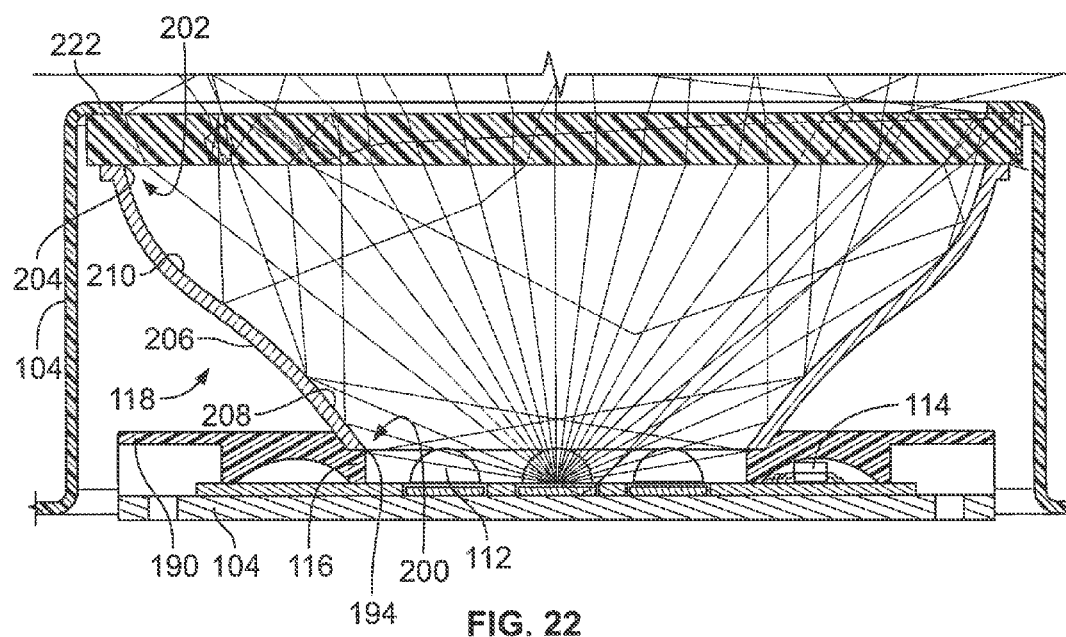


FIG. 22

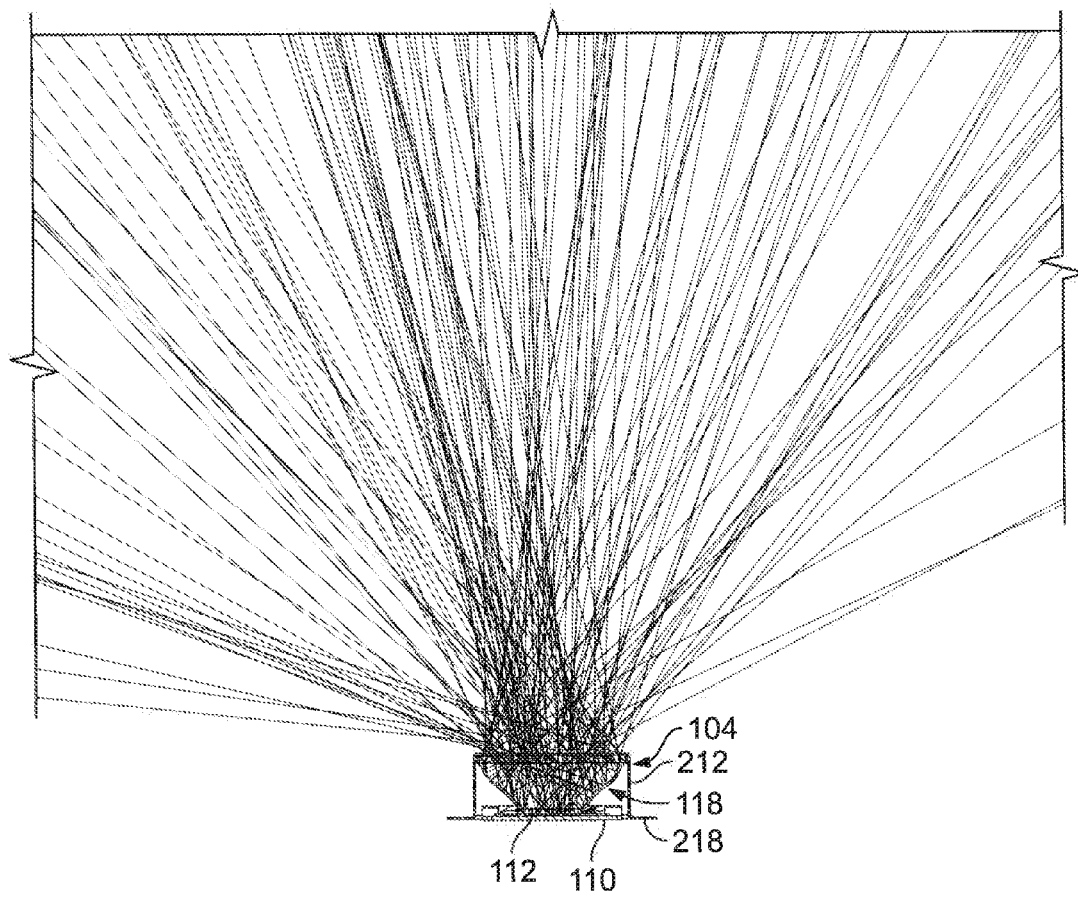


FIG. 23

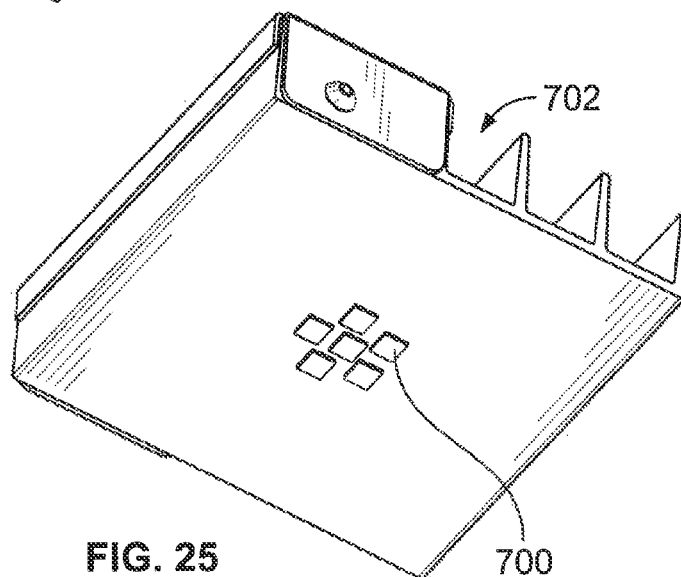
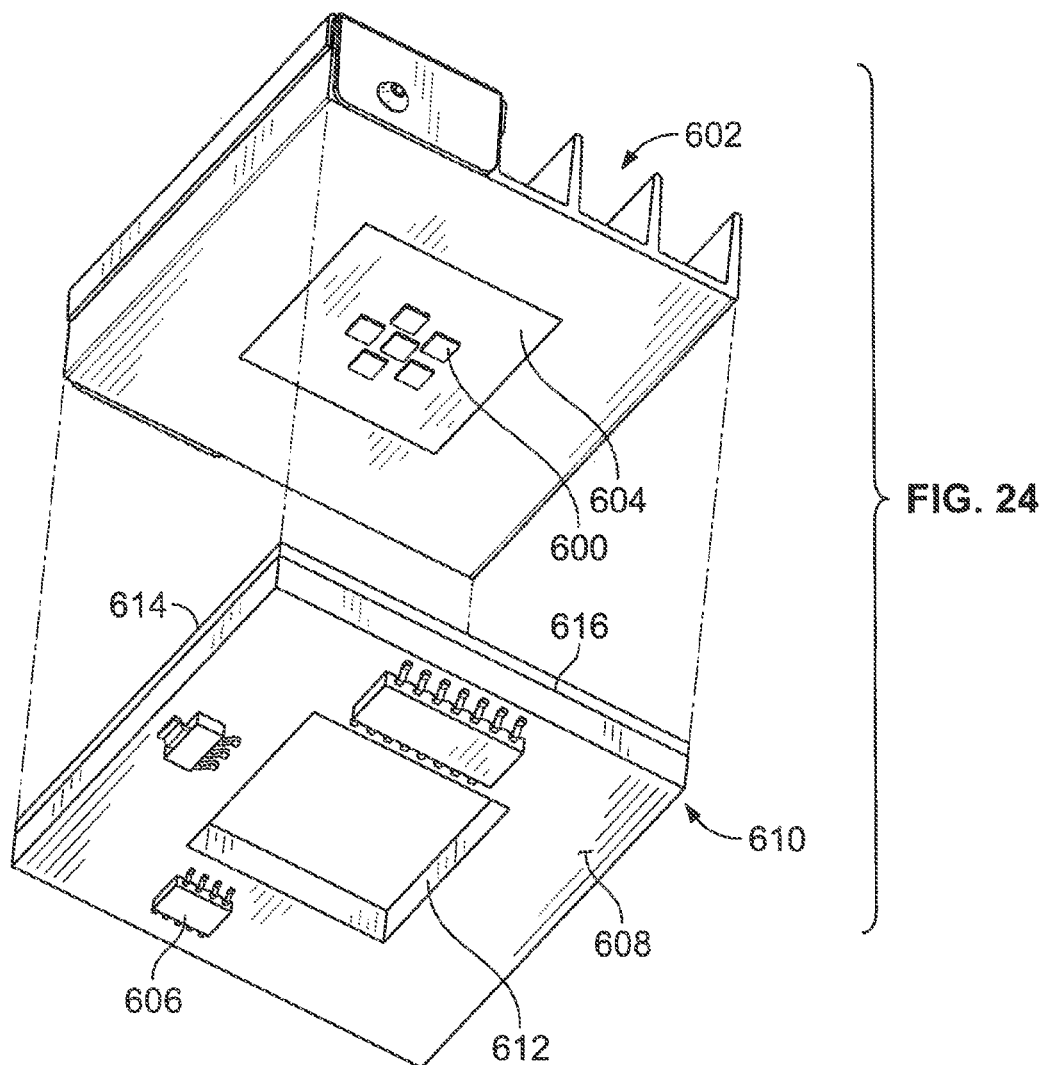
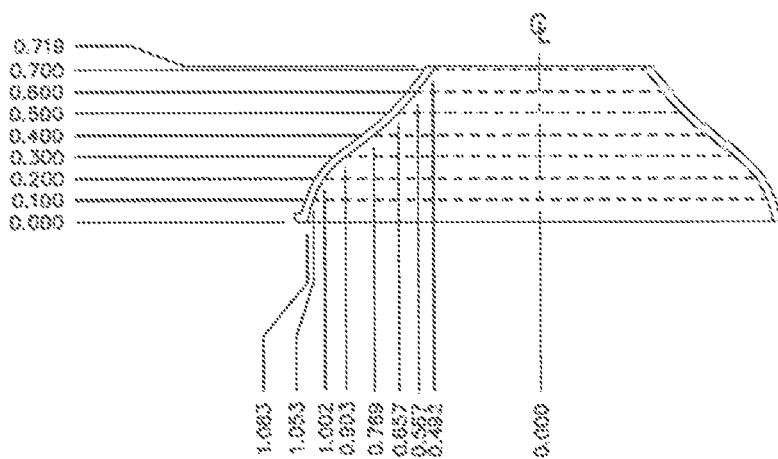


FIG. 26



1

LED DOWNLIGHT**CROSS REFERENCE TO RELATED APPLICATIONS**

Not applicable

REFERENCE REGARDING FEDERALLY SPONSORED RESEARCH OR DEVELOPMENT

Not applicable

SEQUENTIAL LISTING

Not applicable

BACKGROUND OF THE INVENTION**1. Field of the Invention**

The present inventive subject matter relates to solid state lighting devices.

2. Background of the Invention

Solid state light emitters including organic, inorganic, and polymer light emitting diodes (LEDs) may be utilized as an energy-efficient alternative to more traditional lighting systems. About ninety percent of the electricity consumed by an incandescent bulb is released as heat rather than light. In contrast to a typical 60-watt incandescent bulb that has an efficacy of about 13.3 to 14.2 lumens per watt, an LED light source can provide up to 200 lumens per watt.

Many modern lighting applications utilize high power solid state emitters to provide a desired level of brightness. High power solid state emitters generate heat that must be dissipated to prolong the life of the emitters. Generally, the lifetime of an LED is inversely related to the operating junction temperature thereof. Therefore, thermal management of the junction temperature is an important design consideration of a lighting device (or fixture) incorporating one or more LED's. For example, limiting the junction temperature of a particular LED manufactured by the assignee of the present application below 85° C. can result in an LED lifetime of approximately 50,000 hours. Operation of a such a solid state light source at a junction temperature of higher temperatures of 95° C., 105° C., 115° C., and 125° C. may result in life durations of 25,000 hours, 12,000 hours, 6,000 hours, and 3,000 hours, respectively. Many solid state lighting systems utilize a heat exchanger that dissipates heat into the ambient environment. Heat exchangers may be sized and shaped to maintain a specific solid state emitter junction temperature so as to obtain a desired life of the solid state emitters.

LEDs operate more efficiently when powered by a direct current (DC) voltage rather than an alternating current (AC) voltage. Solid state light emitting devices may typically be operated by control circuitry including an AC to DC converter because power is supplied to the device as AC voltage. The conversion circuitry (which may utilize a bulky transformer and one or more solid state electrical elements, such as diodes and one or more transistors) may be incorporated within the device thereby increasing fixture costs and space requirements. A more ready acceptance of LED lighting fixtures could be realized if size and costs could be reduced.

Heat exchangers are made of thermally conductive materials such as aluminum or an aluminum alloy. The heat flux that a heat exchanger can conduct depends on a variety of factors, such as the type and density of material, the surface

2

area, the heat exchanger geometry, the thicknesses of the various surfaces, the convection coefficient of the ambient air flow, etc.

Further, a lighting device typically includes a reflector and a diffuser to direct light emitted from the solid state emitters. The reflector is made of a reflective material, such as aluminum or silvered plastic. The shape of the reflector in combination with the diffuser and LED array size, array configuration, and relative location of the array to other optical components produces a specific beam spread. The beam spread is the volume of space defined by the generally frusto-conical locus of points at which the intensity of the light is equal to 50% of the maximum lumen output. The beam spread determines the coverage of a single lighting unit as well as the spacing and quantity required when a plurality of such units are used for uniform illumination of a surface.

SUMMARY OF THE INVENTION

According to one aspect of the present invention, a lighting device comprises a light emitting diode (LED), a heat exchanger in which the LED is disposed in heat transfer relationship, a reflector having a proximal end disposed about the LED, and a diffuser disposed on a distal end of the reflector. The lighting device has a weight to lumen ratio of no greater than about 2.5 g. per lumen (0.09 oz. per lumen).

According to another aspect of the present invention, a lighting device comprises a substrate including a first surface on which is disposed an LED, a heat exchanger mounted directly to a second surface of the substrate opposite the first surface, a reflector having a proximal end disposed about the LED array, and a diffuser disposed on a distal end of the reflector. A profile to lumen ratio of the device is no greater than about 1.2 cm² per lumen (0.2 in² per lumen).

According to a further aspect of the present invention, a lighting device comprises a substrate, an LED array mounted on a first surface of the substrate, circuit components mounted on the first surface of the substrate and coupled to the LED array, a heat exchanger mounted on a second surface of the substrate, a reflector disposed about the LED array, and a diffuser. The circuit components are adapted to control electrical power applied to the LED array. The reflector has a reflection surface that is convex on a first side of an inflection locus and concave on a second side of the inflection locus, and the first side of the inflection locus is proximate the LED array. The diffuser is adjacent to the second side of the inflection locus of the reflector.

According to yet another aspect of the present invention, a lighting device comprises a substrate having a surface, an LED array mounted on the surface of the substrate, and circuit components mounted on the surface of the substrate, coupled to the LED array, and adapted to receive power from a power source. The lighting device has a weight to lumen ratio of no greater than about 2.5 g. per lumen (0.09 oz. per lumen).

Other aspects and advantages of the present invention will become apparent upon consideration of the following detailed description and the attached drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is an isometric view of a first embodiment of a lighting device from above;

FIG. 2 is an isometric view of the first embodiment of the lighting device from below;

FIG. 3 is a plan view of the first embodiment of the lighting device;

3

FIG. 4 is a side elevational view of the first embodiment of the lighting device;

FIG. 5 is a cross sectional view taken generally along the lines 5-5 of FIG. 4;

FIG. 6 is an exploded isometric view of the first embodiment of the lighting device from above;

FIG. 7 is an exploded isometric view of the first embodiment of the lighting device from below;

FIG. 8 is an isometric view of the a exchanger, a mounting collar, and associated components;

FIG. 9 is a plan view of the heat exchanger, the mounting collar, and associated components;

FIG. 10 is an elevational view of the heat exchanger, the mounting collar 116, and associated components;

FIG. 11 is a cross sectional view taken generally along the lines 11-11 of FIG. 10;

FIG. 12 is an isometric view of a second embodiment of a lighting device from above;

FIG. 13 is an isometric view of the second embodiment of the lighting device from below;

FIG. 14 is a cross sectional view taken generally along the lines 14-14 of FIG. 13;

FIG. 15 is an isometric view of the third embodiment of a lighting device from above;

FIG. 16 is an isometric view of the third embodiment of the lighting device from below;

FIG. 17 is a cross sectional view taken generally along the lines 17-17 of FIG. 15;

FIG. 18 is an isometric view of a fourth embodiment of a lighting device from above;

FIG. 19 is a cross sectional view taken generally along the lines 19-19 of FIG. 18;

FIG. 20 is a plan view of the fourth embodiment of the lighting device from below;

FIG. 21 is a light ray diagram of an outer LED;

FIG. 22 is a light ray diagram of an inner LED;

FIG. 23 is a light ray diagram of an array of LEDs;

FIG. 24 is an isometric view of a second embodiment of a heat exchanger and driver components;

FIG. 25 is an isometric view of a third embodiment of a heat exchanger and driver components; and

FIG. 26 is a cross sectional view of the reflector illustrating sample dimensions thereof (in inches).

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

FIGS. 1-11, 21-23, and 26 illustrate a first embodiment of a luminaire in the form of a lighting device 100 of the present invention. The lighting device 100 comprises a light engine 101 attached to a heat exchanger 102 by a mounting collar 104. The light engine 101 includes a substrate 110 having an LED array 112, a driver circuit 114, and a centering ring 116 mounted thereon, a reflector 118, and a diffuser 120. The lighting device 100 further comprises a trim ring 106, a housing 108, and means for mounting the lighting device 100 in a can or other existing housing that is, in turn, mounted in a ceiling or other surface.

Referring specifically to FIGS. 6, 7, and 11, the substrate 110 has a first side 122 to which an electrically insulative (or dielectric) and thermally conductive coating or cover layer 124 is applied. The electrical isolation and thermal conductivity characteristics of the coating or cover layer 124 depend in part on the thickness of the layer, which can range from 10 to 100 μm . The heat exchanger 102 abuts the coating or cover layer 124 and is thus in thermal communication with the first side 122 of the substrate 110. The substrate 110 is held against

4

the heat exchanger 102 by the mounting collar 104 when used in combination with the centering ring 116, the reflector 118, and the diffuser 120 as noted in greater detail below.

The LED array 112 and driver circuit 114 are disposed on a second side 126 of the substrate 110. The lighting device 100 of the present invention utilizes blue-white LED dies with yellow phosphor coated on the die encapsulants. The LED array 112 includes a number, for example, three LED strings, and each LED string has one or more individual LED's. The driver circuit 114 directly receives AC power from a household or commercial power source and converts AC power at 110 volts, 60 Hz. into AC power suitable to drive the LED array 112. In the preferred embodiment, the driver circuit 114 provides line voltage to power the LED array 112. In this arrangement, the LED array 112 is divided into segments, and as the line voltage rises, the LED segments turn on in series. As the line voltage falls, the LED segments are turned off. The conversion into suitable AC power by the driver circuit requires fewer electrical components and space than the typical conversion of AC voltage to DC voltage, thereby reducing the cost of the circuit components and allowing the driver circuit 114 to be mounted directly onto the substrate and to fit into a much smaller space than a driver circuit that includes an AC to DC converter. One example of a driver circuit 114 suitable for the present invention is disclosed in U.S. Patent Application Publication No. 2013/0026923, filed Jan. 27, 2012, entitled "Solid State Lighting Apparatus and Methods of Forming", the disclosure of which is hereby incorporated by reference herein. The driver circuit of such patent application is disclosed as being mounted on a rectangular substrate, whereas the driver circuit of the preferred embodiment of the present invention is mounted on a circular substrate as shown in U.S. Design Pat. No. D708,155, filed Apr. 20, 2012, entitled "Solid State Lighting Apparatus" (assignee reference P1557US1), the disclosure of which is also hereby incorporated by reference herein. Applicants further incorporate by reference herein the disclosures of U.S. Provisional Application Ser. No. 61/581,923, filed Dec. 30, 2011, U.S. Pat. No. 8,742,671, entitled "Solid State Lighting Apparatus and Methods Using Integrated Driver Circuitry", filed Jul. 28, 2011, U.S. Patent Application Publication No. 2013/0069535, entitled "Solid-State Lighting Apparatus and Methods Using Energy Storage", filed Sep. 16, 2011, and U.S. Patent Application Publication No. 2013/0069536, entitled "Solid-State Lighting Apparatus and Methods Using Current Diversion Controlled by Lighting Device Bias States", filed Sep. 16, 2011. In some embodiments, the driver circuit 114 or power supply for the LED array 112 is directly on the second side 126 of the substrate 110. In other embodiments, the power supply directly connects to the substrate 110.

The number of LEDs (otherwise referred to as dies) may vary between strings. In the preferred embodiment, the LED array 112 comprises three strings of two LEDs each connected together in series and therefore the LED array 112 of the preferred embodiment has six LEDs. Varying the number of LEDs and the power level supplied thereto varies the lumen output. For example, a low-power lighting device 100 that utilizes high voltage LEDs may require about 14 watts to produce about 770 lumens. A medium-power lighting device that utilizes high voltage LEDs may require about 21 watts to produce about 1,360 lumens. Still further, a high-power lighting device that utilizes high voltage LEDs may require about 27 watts to produce about 1,800 lumens. According to the present invention, each of the low-, medium-, and high-power lighting devices 100 has a minimum efficacy of about 50 lumens per watt. Therefore only approximately 9.0%, 22.7%,

5

and 25.0% of the electricity consumed by the low-, medium-, and high-power lighting devices **100**, respectively, is released as heat rather than light. Examples of suitable LEDs include, but are not limited to, XLamp XM-L LEDs (high voltage LEDs) or XLamp XT-E White LEDs (high voltage LEDs) manufactured and sold by Cree, Inc. of Durham, N.C. As the substrate **110** is in thermal connection with the heat exchanger **102**, heat generated by the LED array **112** is directed into the substrate **110** and then dissipated into the ambient air by the heat exchanger **102**.

Referring to FIGS. 6 and 7, the substrate **110** is circular, as noted above, and has three notches **128a**, **128b**, **128c** positioned at 90 degree intervals along an outer edge **130**. The LED array **112** disposed on the second side **126** of the substrate **110** is encircled by the centering ring **116**. The driver circuit **114** is disposed between the centering ring **116** and the outer edge **130** of the substrate **110**. As shown in FIG. 11, wires **132** extend from a connector mounted on the second side **126** through the notch **128c** of the substrate **110** to a splice box **170** forming a part of the heat exchanger **102** as described in greater detail below.

Referring to FIGS. 8-11, the heat exchanger **102** has a planar, rectangular or square base plate **148** and a plurality of longitudinal fins **150**, **152**, **154**, **156**, **158** extending away from the base plate **148**. A hollow, longitudinally-split tube **160** having ends **162a**, **162b** is disposed in the space between the fins **150**, **152** on the base plate **148**. A substantially U-shaped cover **164** is disposed over the space between the fins **150**, **152** such that side flanges **166**, **168** are disposed along facing side surfaces of the fins **150**, **152** to form the splice box **170**. Fasteners in the form of screws **172**, **174** extend through holes in end flanges **176**, **178** of the cover **164** into the ends **162a**, **162b** to secure the cover **164** on the heat exchanger **102**. The heat exchanger is made of any suitable metallic or non-metallic material, such as extruded aluminum.

In each of the embodiments disclosed herein, the heat exchanger (i.e., the base plate, fins, longitudinally-split tube, and splice box cover and associated screws alone) preferably has a weight of approximately 113 (4 oz.), preferably no greater than about 198 g. (7 oz.), preferably between about 85 g. (3 oz.) and about 170 g. (6 oz.), and more preferably between about 99 g. (3.5 oz.) and about 142 g. (5 oz.).

Wires **144** enter the splice box **170** through a grommet **182** as shown in FIG. 1 and are spliced with the wires **132** to connect to the connector on the driver circuit **114** of the substrate **110**. The wires **144** are connected to a harness **134** (diagrammatically shown in FIG. 1) and an Edison-type plug **136**. The wires **144** include two power leads from the lighting device **100** to the harness **134** and a ground wire that is secured to the interior of a recessed can light housing. The Edison-type plug **136** may be screwed into an Edison-type socket to provide an alternating current through wires **132**, **144** to the driver circuit **114**.

Two fasteners **188** in the form of screws extend through notches **128a**, **128b** in the substrate **110** and through holes **180a**, **180b** between the fins **152**, **154** on the base plate **148**. Two diametrically opposed anchor arms **190** of the centering ring **116** extend outwardly from a central ring portion **192** and are engaged by the two fasteners **188** that extend through the notches **128a**, **128b** of the substrate **110** to position the centering ring **116**.

As seen in FIGS. 5 and 11, the central ring portion **192** includes an annular lip **194** that surrounds the LED array **112**. The annular lip **194** defines a recess that receives a proximal end **200** of the reflector **118**. The interior surface **198** of the annular lip **194** complements the curvature of the proximal

6

end **200** of the reflector **118** in order to hold the reflector **118** in place relative to the LED array **112** and to provide electrical isolation between the substrate **110** and the reflector **118** when a metallic reflector is used.

The reflector **118** has a distal end **202** opposite the proximal end **200** that includes an aperture **204** as seen in FIGS. 11, 21, and 22. The aperture **204** is covered by the diffuser **120**, which is adjacent to and abuts an outwardly directed flange of the reflector **118**. An inflection point **206** in the reflector **118** between the proximal and distal ends **200**, **202** separates a convex inner reflective surface **208** and a concave inner reflective surface **210**, respectively.

The convex and concave inner reflective surfaces **208**, **210** of the reflector **118** direct the rays of light emitted from the LEDs in a crossfire manner throughout the reflector **118** and through the diffuser **120** as shown in FIGS. 21-23. More specifically, the convex inner reflective surface **208** provides crossfire illumination of the light rays and the concave inner reflective surface **210** directs the light rays. The reflector **118** and the diffuser **120** collectively produce a beam spread having a luminaire spacing to mounting height ratio of between about 0.5 and about 1.5 depending on the design of the concave inner reflective surface **210**. In the illustrated embodiment, the reflector **118** and the diffuser **120** have a luminaire spacing to mounting height ratio of 1.0. A plurality of lighting devices **100** of the preferred embodiment spaced from adjacent devices at a distance equal to the mounting height of the lighting devices **100** above a planar surface to be illuminated provides a substantially uniform illumination of the planar surface. For example, a plurality of lighting devices spaced eight feet apart in a room with eight-foot ceilings will provide substantially uniform illumination of the floor of the room. FIG. 26 illustrates sample dimensions of the reflector **118**, it being understood that the actual dimensions according to the present invention are not limited to same.

It should be noted that the diffuser **120** material and dimensions are selected to scatter light such that the individual LEDs of the LED array **112** appear as a single light source. An example of a suitable material for the diffuser **120** is Solite™, manufactured and sold by AGC Solar of Tokyo, Japan.

Referring to FIGS. 5 and 11, the mounting collar **104** is sized to contain the substrate **110**, the centering ring **116**, the reflector **118**, and the diffuser **120** within a cavity **211**. The mounting collar **104** includes a cylindrical main portion **212** extending between a proximal end **214** and a distal end **216**. The proximal end **214** includes an outwardly directed flange **218** disposed in abutment with the base plate **148** of the heat exchanger **102**. The flange **218** includes a plurality of holes through which fasteners **220** are secured into the plate **148** of the heat exchanger **102**. A collar lip **222** extends inwardly at the distal end **216** of the mounting collar **104**. When assembled, the substrate **110**, the centering ring **116**, the reflector **118**, and the diffuser **120** are securely held in place within the cavity **211** against the heat exchanger **102** by the collar lip **222** of the mounting collar **104**.

In the preferred embodiment, the LED array **112** and the driver circuit **114** mounted on the second side **126** of the substrate **110** are disposed within the flange **218** of the mounting collar **104**. The LED array **112** is disposed on the second surface **126** of the substrate **110** within the proximal end **200** of the reflector **118**, while the driver circuit **114** is disposed on the second surface **126** of the substrate **110** outside of the proximal end **200** of the reflector **118**. In some embodiments, the wires **132** providing AC power to the driver circuit **114** may extend through the holes **180c**, **128c** of the base plate **148** and the substrate **110**, respectively, into the cavity **211**. In

other embodiments, the substrate **110** alone or in combination with the mounting collar **104** is directly mounted onto the heat exchanger **102**.

Alternatively, in an embodiment shown in FIG. **24**, a plurality of LEDs **600** is secured by any suitable non-electrically conductive or electrically insulated means (e.g., thermally conductive adhesive and/or fasteners) to the heat exchanger **602** together with any suitable intervening electrically non-conductive structure or material **604** including a thermally conductive submount (e.g., a circuit board) or a film such as Kapton®, manufactured by DuPont of Wilmington, Del. In the illustrated embodiment of FIG. **24**, the driver circuitry **606** is mounted on a first side **608** of a square (or other shape) substrate **610** having an inner aperture **612** that is sized to surround the plurality of LEDs **600** when assembled. An electrically insulative and thermally conductive intervening layer or coating **614** is optionally applied to a second side **616** of the substrate **610**. The substrate **610** is mounted to the heat exchanger in any suitable fashion including but not limited to the use of fasteners or a thermally conductive adhesive.

Further, in an embodiment shown in FIG. **25**, a plurality of LEDs **700** is secured directly to the heat exchanger **702** by a thermal cement or other suitable means. In this embodiment, each LED must be designed to have at least one electrode that is not in electrical contact with the material of the heat exchanger, if the heat exchanger is made of electrically conductive material(s). The driver circuitry may be mounted on any suitable structure that is secured (or not secured, if desired) to the heat exchanger.

Referring again to FIGS. **4-7**, the housing **108** has a cylindrical housing portion **224** and a frusto-conical cone-shaped housing portion **226**. The cylindrical housing portion **224** is dimensioned to fit securely about the cylindrical portion **212** of the mounting collar **104** and is further secured thereto by two diametrically opposed fasteners **225**. The cone portion **226** includes an outwardly directed annular flange **228** that receives a shouldered annular surface of the trim ring **106** so that the trim ring **106** sits atop the flange **228**. Referring to FIG. **5**, the trim ring **106** includes a tapered, annular surface **230** that is visible from the interior of the room. If desired, a different trim ring may be substituted for the illustrated trim ring. In some embodiments, as seen in the FIGS., the trim ring **106** is disposed in thermal communication with the heat exchanger via components including the mounting collar and the housing portion, which may be made of thermally conductive metal(s). In other embodiments, the trim ring may be thermally coupled to the heat exchanger by one or more additional or alternative components. In all these embodiments, the trim ring can dissipate heat. In other embodiments, one or more additional or alternative structures are disposed in thermal communication with the LED array and the heat exchanger is in thermal communication with one or more of the trim ring, the LED array, and/or any other heat transferring and/or dissipating structure(s). Still further in other embodiments, the trim ring, the housing, the mounting collar, and other components may sufficiently dissipate heat such that a heat exchanger is not necessary. In U.S. Pat. No. 7,722,220, the disclosure of which is incorporated by reference herein, the trim ring serves as the thermal conduction element, and heat generated by solid state emitters is conducted through the trim ring and dissipated into the ambient environment of the room.

In one embodiment, the lighting device **100** is equipped with two torsion spring brackets **232**, **234** and two torsion springs **236**, **238** as shown in FIGS. **1-7** for mounting into a recessed can light housing. Each bracket **232**, **234** has a first portion **242** perpendicular to the base plate **148** of the heat

exchanger **102**, a second portion **244** that extends away from the lighting device **100** at an angle, and a third portion **246**. Bracket fasteners **248** (FIGS. **4-6**) extend through holes in each of the first portions **242** and the fins **150**, **158**. Each torsion spring **236**, **238** is attached to each third portion **246** by spring fasteners **250**. Each torsion spring **236**, **238** is made of a flexible spring material to permit elongate legs **236a**, **236b**, **238a**, **238b** to be compressed toward one another so that hook portions **236c**, **238c** can be inserted into slots (not shown) in the can light housing. The legs **236a**, **236b**, **238a**, **238b** may then be released and the device **100** may be pushed up into the can light housing such that the flange **228** and the trim ring **106** abut the ceiling or other surface and/or a flange (not shown) of the can light housing and the remainder of the lighting device is disposed in the can light housing.

Referring to FIGS. **1-11**, sample dimensions of the lighting device **100** are provided in Table 1 below. In the preferred embodiment, the lighting device **100** excluding the wiring **132**, **144** preferably has a weight of approximately 368 g. (13 oz.), preferably no greater than about 482 g. (17 oz.), preferably between about 283 g. (10 oz.) and about 455 g. (16 oz.), and more preferably between about 312 g. (11 oz.) and about 425 g. (15 oz.). The lighting device **100** preferably has a weight (as defined above) to lumen ratio of approximately 0.3 g. per lumen (0.01 oz. per lumen), preferably no greater than about 1 g. per lumen (0.035 oz. per lumen), preferably between about 0.14 g. per lumen (0.005 oz. per lumen) and about 0.9 g. per lumen (0.03 oz. per lumen), and more preferably between about 0.2 g. per lumen (0.007 oz. per lumen) and about 0.6 g. per lumen (0.02 oz. per lumen).

TABLE 1

Sample dimensions of lighting device 100	
A	102 mm (4 in)
B	76 mm (3 in)
C	102 mm (4 in)
D	89 mm (3.5 in)
E	89.6 mm (3.53 in)
F	17.3 mm (0.68 in)
G	21.6 mm (0.85 in)
H	26.3 mm (1.035 in)
I	62.5 mm (2.46 in)

In the preferred embodiment, the heat exchanger **102** including the base plate and fins has a size **S1** calculated as follows:

$$S1 = \frac{\text{length of base plate} \times \text{width of base plate} \times \text{overall height of the heat exchanger}}{\text{height of the heat exchanger}}$$

wherein the overall height of the heat exchanger includes the thickness of the base plate plus the height of the fins. Preferably, **S1** is approximately 172 cm³ (11 in³), preferably no greater than about 525 cm³ (32 in³), preferably between about 84 cm³ (5 in³) and about 449 cm³ (27 in³), and more preferably between about 110 cm³ (7 in³) and about 402 cm³ (25 in³). The heat exchanger **102** preferably has a size to lumen ratio of approximately 0.141 cm³ per lumen (0.000840 in³ per lumen), preferably no greater than about 1 cm³ per lumen (0.06 in³ per lumen), preferably between about 0.042 cm³ per lumen (0.003 in³ per lumen) and about 0.9 cm³ per lumen (0.05 in³ per lumen), and more preferably between about 0.06 cm³ per lumen (0.004 in³ per lumen) and 0.5 cm³ per lumen (0.03 in³ per lumen). Additionally, the heat exchanger **102** preferably has a weight of approximately 113 g. (4 oz.), preferably no greater than about 198 g. (7 oz.), preferably between about 85 g. (3 oz.) and about 170 g. (6 oz.), and more preferably between about 99 g. (3.5 oz.) and about 142 g. (5

oz.). The heat exchanger **102** preferably has a weight to lumen ratio of approximately 0.09 g. per lumen (0.003 oz. per lumen), preferably no greater than about 0.4 g. per lumen (0.014 oz. per lumen), preferably between about 0.04 g. per lumen (0.001 oz. per lumen) and about 0.3 g. per lumen (0.01 oz. per lumen), and more preferably between about 0.06 g. per lumen (0.002 oz. per lumen) and about 0.2 g. per lumen (0.007 oz. per lumen).

Further, the light engine **101**, the heat exchanger **102**, and the mounting collar **104** have a combined size **S2** calculated as follows:

$$S2 = S1 + (\pi * (\text{radius of mounting collar})^2 * \text{height of mounting collar})$$

Preferably, **S2** is approximately 255 cm³ (16 in³), preferably no greater than about 756 cm³ (46 in³), preferably between about 123 cm³ (8 in³) and about 637 cm³ (39 in³), and more preferably between about 170 cm³ (10 in³) and about 557 cm³ (34 in³). The light engine **101**, the heat exchanger **102**, and the mounting collar **104** preferably have a size to lumen ratio of approximately 0.2 cm³ per lumen (0.01 in³ per lumen), preferably no greater than about 1.5 cm³ per lumen (0.09 in³ per lumen), preferably between about 0.06 cm³ per lumen (0.004 in³ per lumen) and about 1 cm³ per lumen (0.06 in³ per lumen), and more preferably between about 0.09 cm³ per lumen (0.005 in³ per lumen) and about 0.7 cm³ per lumen (0.04 in³ per lumen).

The lighting device **100** excluding the wiring **144**, the trim ring **106**, torsion spring brackets **232**, **234**, and two torsion springs **236**, **238** has an overall size **S3** calculated as follows:

$$S3 = S2 + (\pi * \text{height of cone housing portion} / 3 * ((\text{smaller radius of cone housing portion})^2 + (\text{smaller radius of cone housing portion})(\text{larger radius of cone housing portion}) + (\text{larger radius of cone housing portion})^2))$$

Preferably, **S3** is approximately 524 cm³ (32 in³), preferably no greater than about 2,004 cm³ (122 in³), preferably between about 148 cm³ (9 in³) and about 1,530 cm³ (93 in³), and more preferably about 352 cm³ (21 in³) to about 1,157 cm³ (71 in³). The lighting device **100** preferably has a size to lumen ratio of approximately 0.4 cm³ per lumen (0.02 in³ per lumen), preferably no greater than about 4 cm³ per lumen (0.2 in³ per lumen), preferably between about 0.07 cm³ per lumen (0.004 in³ per lumen) and about 3 cm³ per lumen (0.2 in³ per lumen), and more preferably between about 0.2 cm³ per lumen (0.01 in³ per lumen) and about 1.5 cm³ per lumen (0.09 in³ per lumen).

A profile **P1** of the lighting device **100** is defined as the diameter **C** (FIG. 5) of the distal end of the cone portion **226** including the flange **228** times the distance **A** (FIG. 4) from an outermost edge of the trim ring **106** to the upper surface of the heat exchanger **102** including the splice box cover **164** and the grommet **182**, and excluding the wiring **144**. Preferably, the lighting device **100** has a profile **P1** of approximately 104 cm² (16 in²), preferably no greater than about 310 cm² (48 in²), preferably between about 52 cm² (8 in²) and about 248 cm² (38 in²), and more preferably between about 97 cm² (15 in²) and about 194 cm² (30 in²). Further, the lighting device **100** preferably has a profile **P1** to lumen ratio of approximately 0.08 cm² per lumen (0.01 in² per lumen), preferably no greater than about 0.6 cm² per lumen (0.09 in² per lumen), preferably between about 0.03 cm² per lumen (0.005 in² per lumen) and about 0.5 cm² per lumen (0.08 in² per lumen), and more preferably between about 0.05 cm² per lumen (0.008 in² per lumen) and about 0.3 cm² per lumen (0.05 in² per lumen).

In an embodiment shown in FIGS. 12-14, the lighting device **300** includes a lens **302** to block the entrance of steam

and water into the lighting device **100** when used in a shower or other wet environment. Except for the structures to maintain the lens **302** in place as described below, the lighting device **300** including the parameters is identical to the lighting device **100**.

An exposed surface **304** of the lens **302** includes a plurality of concentric, annular ribs **306**. The lens **302** rests atop an inner annular ledge **308** of a trim ring **310**. The trim ring **310** further includes a cylindrical portion **312** from which two diametrically opposed tabs **314**, **316** extend. The tabs **314**, **316** are disposed between the windings of two torsion springs **318**, **320**. The torsion springs **318**, **320** are secured to the tabs by any suitable means, such as fasteners (not shown).

The second embodiment of the lighting device **300** excluding the wiring and the lens **302** has a weight of approximately 368 g. (13 oz.), preferably no greater than about 482 g. (17 oz.), preferably between about 283 g. (10 oz.) and about 455 g. (16 oz.), and more preferably between about 312 g. (11 oz.) and about 425 g. (15 oz.). The lighting device **100** preferably has a weight (as defined above) to lumen ratio of approximately 0.3 g. per lumen (0.01 oz. per lumen), preferably no greater than about 1 g. per lumen (0.035 oz. per lumen), preferably between about 0.14 g. per lumen (0.005 oz. per lumen) and about 0.9 g. per lumen (0.03 oz. per lumen), and more preferably between about 0.2 g. per lumen (0.007 oz. per lumen) and about 0.6 g. per lumen (0.02 oz. per lumen).

FIGS. 15-17 illustrate another embodiment of the invention. In this embodiment, the lighting device **400** comprises an eyeball type device that includes a multi-component housing **402** to enable a beam of light to be rotated about a vertical axis of rotation **404** and a horizontal axis of rotation **406**. Except for the structures to enable rotation of the beam of light as described below, the lighting device **400** including the parameters is identical to the lighting device **100** of the first embodiment.

The housing **402** includes a housing ring **408**, an outer housing **410**, and an inner housing **412**. The housing ring **408** is cylindrical with a housing ring ledge **414** extending annularly from the bottom thereof that rests atop and is rotatable with respect to a trim ring **416**. The trim ring includes a cylindrical portion **418** from which two diametrically opposed tabs **420**, **422** extend. The tabs **420**, **422** are inserted between the windings of two torsion springs **424**, **426**. The torsion springs **424**, **426** are secured to the tabs **420**, **422** by any suitable means, such as fasteners (not shown).

The outer housing **410** has a frusto-spherical shape having a proximal end **428** adjacent an LED array **430** and a distal end **432**. The outer housing **414** is rotatable about two diametrically opposed fasteners **434** that are inserted through holes in the housing ring **408** and the outer housing **410**. The inner housing **412** includes a cylindrical portion **436** adjacent a proximal end **438** and a corrugated frusto-conical cone-shaped portion **440** adjacent a distal end **442**. The cylindrical portion **436** is dimensioned to fit securely about a mounting collar **444**.

The housing **402** is secured to a heat exchanger **446** by two brackets **448**, **450**. A first portion **452** of the each bracket **448**, **450** complements the curvature of the outer housing **410** and a second portion **454** extends perpendicular to a base plate **452**. Fasteners **455** such as screws are inserted through the outer housing **410** and the first portion **452** of each bracket **448**, **450** and through the second portion **454** and fins **458**, **460** that extend from a base plate **447** of a heat exchanger **446**.

Referring to FIGS. 15-17, sample dimensions of the lighting device **400** are provided in Table 2 below. In the preferred embodiment, the lighting device **400** has a weight (excluding wiring) of approximately 680 g. (24 oz.), and preferably no

11

greater than about 850 g. (30 oz.). Preferably, the lighting device **400** has a weight to lumen ratio of approximately 0.5 g. per lumen (0.02 oz. per lumen), and preferably no greater than about 1.7 g. per lumen (0.06 oz. per lumen).

TABLE 2

Sample dimensions of lighting device 400	
J	65 mm (2.6 in)
K	39 mm (1.5 in)
L	100 mm (3.9 in)
M	124 mm (4.9 in)
N	98 mm (3.9 in)

The lighting device **400** excluding the wiring preferably has an overall size **S4** excluding the wiring and the trim ring **416** calculated as follows:

$$S4 = S1 + (\pi * \text{height of the outer housing}) / 3 * (2 * (\text{radius of the largest diameter in the outer housing})^2 + (\text{radius of outer housing at the proximal and distal ends})^2)$$

Preferably, **S4** is approximately 944 cm³ (58 in³), preferably no greater than about 1,625 cm³ (99 in³), preferably between about 537 cm³ (33 in³) and about 1,372 cm³ (84 in³), and more preferably between about 678 cm³ (41 in³) and about 1,301 cm³ (79 in³). The lighting device **400** excluding the wiring preferably has a size to lumen ratio of approximately 0.8 cm³ per lumen (0.05 in³ per lumen), preferably no greater than about 3.3 cm³ per lumen (0.2 in³ per lumen), preferably between about 0.3 cm³ per lumen (0.02 in³ per lumen) and about 3.0 cm³ per lumen (0.2 in³ per lumen), and more preferably between about 0.4 cm³ per lumen (0.02 in³ per lumen) and about 2 cm³ per lumen (0.1 in³ per lumen).

In this embodiment, the profile **P2** is defined as the diameter **M** (FIG. 17) of the outer housing **410** times the distance **N** (FIG. 17) from the distal end **432** of the outer housing **410** to a distal surface of the heat exchanger **446** including a splice box cover and a grommet, and excluding the wiring. Preferably, the lighting device **400** has a profile **P2** of approximately 122 cm² (19 in²), preferably no greater than about 177 cm² (27 in²), preferably between about 87 cm² (13 in²) and about 161 cm² (25 in²), and more preferably between about 100 cm² (16 in²) and about 148 cm² (23 in²). The lighting device **400** preferably has a profile **P2** to lumen ratio of approximately 0.1 cm² per lumen (0.02 in² per lumen), preferably no greater than about 0.4 cm² per lumen (0.06 in² per lumen), preferably between about 0.04 cm² per lumen (0.006 in² per lumen) and about 0.3 cm² per lumen (0.05 in² per lumen), and more preferably between about 0.06 cm² per lumen (0.009 in² per lumen) and about 0.2 cm² per lumen (0.03 in² per lumen).

In a fourth embodiment shown in FIGS. 18-20, the lighting device **500** is designed for new construction or remodeling. The lighting device **500** includes a housing **502**, a trim ring **504** having a trim ring frame **506**, a mounting system **508**, and a junction box **510**. Except for the structures to enable use of the lighting device **500** for new construction as described below, the lighting device **500** including the parameters is identical to the lighting device **100** of the first embodiment.

Seen in FIGS. 19 and 20, the housing **502** includes an inwardly extending housing flange **512** adjacent a heat exchanger **514**. Two keyed openings **516**, **518** having wide ends **520**, **522** and narrow ends **524**, **526** and two oblong openings **528**, **530** are formed in the housing flange **512**. Four fasteners **532** are inserted partially into a base plate **534** of the heat exchanger **514**. To secure the housing **502** to the heat exchanger **514**, the housing **502** is placed on the heat exchanger **514** such that heads of the fasteners **536** are posi-

12

tioned in the two wide ends **520**, **522** of keyed openings **516**, **518** and the two oblong openings **528**, **530** and the housing **502** is rotated relative to the heat exchanger **514** to cause shanks of the fasteners **532** to move into the narrow ends **524**, **526** of the keyed openings **516**, **518** and the two oblong openings **528**, **530**. The fasteners **532** can then be tightened down to maintain the parts in assembled relationship.

The trim ring frame **506** to which the mounting system **508** is attached rests atop the trim ring **504**. The mounting system **508** may be used to mount the lighting device **500** into a joist space or other cavity. Wires **507** from junction box **510** provide power to an LED array **538** of the lighting device **500**. A thermal protection device housed in a splice box of the heat exchanger **514** may disconnect power to a driver circuit and an LED array in the event of an overtemperature condition.

Referring to FIGS. 18-20, sample dimensions of the lighting device **500** are provided in Table 3 below. In the preferred embodiment, the lighting device **500** excluding wiring **501**, the junction box **510** and associated conduit **507** and mounting structure **511**, and two C-shaped brackets **508** and mounting bracket system **509** of mounting system **508** has a weight of approximately 1,247 g. (44 oz.). The lighting device **500** preferably has a weight (as defined above) to lumen ratio of approximately 1 g. per lumen (0.04 oz. per lumen), preferably no greater than about 2.5 g. per lumen (0.09 oz. per lumen), preferably between about 0.6 g. per lumen (0.02 oz. per lumen) and about 2.5 g. per lumen (0.09 oz. per lumen), and more preferably between 0.7 g. per lumen (0.02 oz. per lumen) and about 2.5 g. per lumen (0.09 oz. per lumen).

TABLE 3

Sample dimensions of lighting device 500	
O	137 mm (5.4 in)
P	305 mm (12 in)
Q	305 mm (12 in)

The lighting device **500** excluding the wiring **501**, the junction box **510** and associated conduit **507** and mounting structure **511**, and two C-shaped brackets **508** and mounting bracket system **509** of mounting system **508** preferably has an overall size **S5** of approximately 1,639 cm³ (100 in³), preferably no greater than about 2,458 cm³ (150 in³), preferably between about 1,229 cm³ (75 in³) and about 2,294 cm³ (140 in³), and more preferably between about 1,393 cm³ (85 in³) and about 2,130 cm³ (130 in³). The lighting device **500** excluding the wiring **501**, the junction box **510** and associated conduit **507** and mounting structure **511**, and two C-shaped brackets **508** and mounting bracket system **509** of mounting system **508** preferably has a size to lumen ratio of approximately 1.3 cm³ per lumen (0.08 in³ per lumen), no greater than about 5 cm³ per lumen (0.3 in³ per lumen), preferably between about 0.6 cm³ per lumen (0.04 in³ per lumen) and about 4.6 cm³ per lumen (0.3 in³ per lumen), and more preferably between about 0.7 cm³ per lumen (0.04 in³ per lumen) and about 2.8 cm³ per lumen (0.2 in³ per lumen).

In this embodiment, the profile **P3** is defined as the distance **Q** (FIG. 20) from an outer surface of the junction box **510** to an opposite edge of the trim ring **504** times the distance **O** (FIG. 19) from an outermost edge of the trim ring **504** to an outer surface of the heat exchanger **514**. In some embodiments, the lighting device **500** preferably has a profile **P3** of approximately 418 cm² (65 in²), preferably no greater than about 619 cm² (96 in²), preferably between about 258 cm² (40 in²) and about 581 cm² (90 in²), and more preferably between about 290 cm² (45 in²) and about 542 cm² (84 in²). Further,

13

the lighting device 500 has a profile P3 to lumen ratio of approximately 0.3 cm² per lumen (0.05 in² per lumen), no greater than about 1.2 cm² per lumen (0.2 in² per lumen), preferably between about 0.1 cm² per lumen (0.02 in² per lumen) and about 1.2 cm² per lumen (0.2 in² per lumen), and more preferably between about 0.2 cm² per lumen (0.03 in² per lumen) and about 0.7 cm² per lumen (0.1 in² per lumen).

Other embodiments of the disclosure including all of the possible different and various combinations of the individual features of each of the foregoing embodiments and examples are specifically included herein.

Industrial Applicability

The lighting devices described herein advantageously include a reflector having a reflection surface that is convex on a first side of an inflection locus and concave on a second side of the inflection locus that provides a beam spread having a luminaire spacing to mounting height ratio of preferably between about 0.5 and about 1.5. Further, particular embodiments of the lighting devices disclosed herein advantageously utilize a compact heat exchanger in thermal communication with an LED array and, optionally, a driver circuit so that overall device size, weight, and profile are reduced and efficacy is maintained above 50 lumens per watt.

Numerous modifications to the present disclosure will be apparent to those skilled in the art in view of the foregoing description. Accordingly, this description is to be construed as illustrative only and is presented for the purposes of enabling those skilled in the art to make and use the present disclosure and to teach the best mode of carrying out the same.

We claim:

1. A lighting device, comprising:

a light emitting diode (LED);

a heat exchanger with which the LED is disposed in heat transfer relationship;

a reflector having a proximal end disposed about the LED;

a driver circuit disposed on a substrate for operating the

LED wherein the driver circuit is adapted to be directly connected to an alternating current (AC) power source;

a diffuser disposed on a distal end of the reflector; and

a mounting collar for maintaining the heat exchanger, the LED, the reflector, and the diffuser in assembled relationship;

wherein a profile to lumen ratio of the entire lighting device is one of no greater than about 1.2 cm² per lumen (0.2 in² per lumen), between about 0.03 cm² per lumen (0.005 in² per lumen) and about 1.2 cm² per lumen (0.2 in² per lumen), and between about 0.05 cm² per lumen (0.008 in² per lumen) and about 0.7 cm² per lumen (0.1 in² per lumen), and

wherein the lighting device has a weight to lumen ratio of no greater than about 2.5 g per lumen (0.09 oz per lumen).

2. The lighting device of claim 1, wherein the weight to lumen ratio is one of between about 0.14 g per lumen (0.005 oz per lumen) and about 2.5 g per lumen (0.09 oz per lumen), and between about 0.5 g per lumen (0.02 oz per lumen) and about 1.7 g per lumen (0.06 oz per lumen).

3. The lighting device of claim 1, wherein a size to lumen ratio of the device is one of no greater than about 5 cm³ per lumen (0.3 in³ per lumen), between about 0.07 cm³ per lumen (0.004 in³ per lumen) and about 4.6 cm³ per lumen (0.3 in³ per lumen), and between about 0.2 cm³ per lumen (0.01 in³ per lumen) and about 2.8 cm³ per lumen (0.2 in³ per lumen).

14

4. The lighting device of claim 1, wherein a size of the heat exchanger to lumen ratio is one of no greater than about 1 cm³ per lumen (0.06 in³ per lumen), preferably between about 0.042 cm³ per lumen (0.003 in³ per lumen) and about 0.9 cm³ per lumen (0.05 in³ per lumen), and more preferably between about 0.06 cm³ per lumen (0.004 in³ per lumen) and 0.5 cm³ per lumen (0.03 in³ per lumen).

5. The lighting device of claim 1, wherein a weight of the heat exchanger to lumen ratio is one of no greater than about 0.4 g per lumen (0.014 oz per lumen), preferably between about 0.04 g per lumen (0.001 oz per lumen) and about 0.3 g per lumen (0.01 oz per lumen), and more preferably between about 0.06 g per lumen (0.002 oz per lumen) and about 0.2 g per lumen (0.007 oz per lumen).

6. The lighting device of claim 1, wherein a profile of the lighting device is one of no greater than about 619 cm² (96 in²), between about 52 cm² (8 in²) and about 581 cm² (90 in²), and between about 97 cm² (15 in²) and about 542 cm² (84 in²).

7. The lighting device of claim 1, wherein the LED is directly mounted on the heat exchanger.

8. The lighting device of claim 1, further including a housing and a trim ring.

9. The lighting device of claim 8, wherein the housing and the trim ring are in heat transfer relationship with the heat exchanger.

10. The lighting device of claim 8, wherein the housing includes an aperture, and the lighting device further comprises a lens displaced about the aperture.

11. A lighting device, comprising:

a substrate including a first surface on which is disposed an LED;

a heat exchanger mounted directly to a second surface of the substrate opposite the first surface;

a reflector having a proximal end disposed about the LED array;

a driver circuit disposed on the substrate for operating the LED wherein the driver circuit is adapted to be directly connected to an AC power source;

a diffuser disposed on a distal end of the reflector; and

a mounting collar for maintaining the heat exchanger, the LED, the reflector, and the diffuser in assembled relationship;

wherein a profile to lumen ratio of the entire lighting device is no greater than about 1.2 cm² per lumen (0.2 in² per lumen).

12. The lighting device of claim 11, wherein the profile to lumen ratio is one of between about 0.03 cm² per lumen (0.005 in² per lumen) and about 1.2 cm² per lumen (0.2 in² per lumen), and between about 0.05 cm² per lumen (0.008 in² per lumen) and about 0.7 cm² per lumen (0.1 in² per lumen).

13. The lighting device of claim 11, wherein a size to lumen ratio of the lighting device is one of no greater than about 5 cm³ per lumen (0.3 in³ per lumen), between about 0.07 cm³ per lumen (0.004 in³ per lumen) and about 4.6 cm³ per lumen (0.3 in³ per lumen), and between about 0.2 cm³ per lumen (0.01 in³ per lumen) and about 2.8 cm³ per lumen (0.2 in³ per lumen).

14. The lighting device of claim 11, wherein a weight of the lighting device to lumen ratio is one of no greater than about 2.5 g per lumen (0.09 oz per lumen), between about 0.14 g per lumen (0.005 oz per lumen) and about 2.5 g per lumen (0.09 oz per lumen), and between about 0.5 g per lumen (0.02 oz per lumen) and about 1.7 g per lumen (0.06 oz per lumen).

15. The lighting device of claim 11, wherein the driver circuit is disposed on the first surface of the substrate.

15

16. The lighting device of claim 11, further including a housing and a trim ring.

17. The lighting device of claim 16, wherein the housing and the trim ring are in heat transfer relationship with the heat exchanger.

18. The lighting device of claim 16, wherein the housing includes an aperture, and the lighting device further comprises a lens displaced about the aperture.

19. A lighting device, comprising:

a substrate;

an LED array mounted on a first surface of the substrate;

circuit components mounted on the first surface of the substrate and coupled to the LED array wherein the circuit components are adapted to control electrical power applied to the LED array;

a heat exchanger mounted on a second surface of the substrate;

a reflector disposed about the LED array, wherein the reflector has a reflection surface that is convex on a first side of an inflection locus and concave on a second side of the inflection locus, and wherein the first side of the inflection locus is proximate the LED array; and a diffuser adjacent to the second side of the inflection locus of the reflector;

wherein the lighting device has a weight to lumen ratio that is one of no greater than 2.5 g per lumen (0.09 oz per lumen), between about 0.14 g per lumen (0.005 oz per lumen) and about 2.5 g per lumen (0.09 oz per lumen), and between about 0.5 g per lumen (0.02 oz per lumen) and about 1.7 g per lumen (0.06 oz per lumen).

20. The lighting device of claim 19, wherein the circuit components are directly coupled to an AC power source.

21. The lighting device of claim 19, wherein the lighting device has a weight that is one of no greater than about 1,247 g (44 oz), between about 283 g (10 oz) and about 850 g (30 oz), and between about 312 g (11 oz) and about 482 g (17 oz).

22. The lighting device of claim 19, wherein the lighting device has a total lumen output of at least about 50 lumens per watt.

23. The lighting device of claim 19, wherein the heat exchanger can dissipate up to about 6.75 watts of heat.

24. The lighting device of claim 19, wherein the substrate maintains a maximum junction temperature of about 85 degrees Celsius.

25. The lighting device of claim 19, further comprising at least one other lighting device, wherein each lighting device has a luminaire spacing to mounting height ratio of between about 0.5 and about 1.5.

26. The lighting device of claim 19, wherein the heat exchanger comprises a plate, a plurality of fins extending from the plate, and a splice box.

27. The lighting device of claim 19, further comprising an Edison-type plug and a wiring harness coupled to the circuit components and wherein the lighting device is adapted to be inserted into an existing recessed can light in a ceiling such that the Edison type plug may be inserted into an Edison-type socket in the can light.

28. The lighting device of claim 27, wherein the lighting device is mounted in one of a wall or a ceiling and wherein a distal surface of the heat exchanger is up to about 102 mm (4 in) away from a proximal surface of the wall or the ceiling.

29. The lighting device of claim 27, wherein the lighting device produces a beam that can be rotated about a vertical axis and a horizontal axis, and wherein a distal surface of the heat exchanger is up to about 65 mm (2.6 in) away from a proximal surface of the wall or the ceiling.

16

30. The lighting device of claim 19, wherein the lighting device is used for new construction, wherein the lighting device is mounted in one of a wall or a ceiling, and wherein a distal surface of the heat exchanger is up to about 137 mm (5.4 in) away from a proximal surface of the wall or the ceiling.

31. The lighting device of claim 19, further comprising a centering ring disposed about the LED array adjacent to the substrate; and

a mounting collar having a mounting flange for maintaining the heat exchanger, the LED array, the reflector, and the diffuser in assembled relationship;

wherein the mounting flange is secured to the heat exchanger by means of fasteners.

32. The lighting device of claim 31, wherein the heat exchanger and the mounting collar have a size that is one of no greater than about 756 cm³ (46 in³), preferably between about 123 cm³ (8 in³) and about 637 cm³ (39 in³), and more preferably between about 170 cm³ (10 in³) and about 557 cm³ (34 in³).

33. A lighting device, comprising:

a substrate having a surface;

an LED array mounted on the surface of the substrate;

circuit components mounted on the surface of the substrate, coupled to the LED array, and adapted to receive power from a power source;

a reflector disposed about the LED array adjacent a proximal end;

a diffuser adjacent to a distal end of the reflector;

a centering ring disposed about the LED array adjacent to the substrate;

a mounting collar having a mounting flange for maintaining the heat exchanger, the LED array, the reflector, and the diffuser in assembled relationship; and

wherein the reflector is disposed within the centering ring, and

wherein the lighting device has a weight to lumen ratio of no greater than about 2.5 g per lumen (0.09 oz per lumen).

34. The lighting device of claim 33, wherein the weight to lumen ratio is one of between about 0.14 g per lumen (0.005 oz. per lumen) and about 2.5 g per lumen (0.09 oz per lumen), and between about 0.5 g per lumen (0.02 oz per lumen) and about 1.7 g per lumen (0.06 oz per lumen).

35. The lighting device of claim 33, wherein the circuit components are coupled to an AC voltage source.

36. The lighting device of claim 33, further comprising

a housing having a first end and a second end; and

a trim ring displaced about the second end;

wherein the mounting flange is secured to the heat exchanger by means of fasteners; and

wherein heat is dissipated through the substrate, the mounting collar, the housing, and the trim ring.

37. The lighting device of claim 33, wherein the lighting device can dissipate up to about 6.75 watts of heat.

38. The lighting device of claim 33, wherein the substrate maintains a maximum junction temperature of approximately 85 degrees Celsius.

39. The lighting device of claim 33, further comprising an Edison-type plug and a wiring harness coupled to the circuit components and wherein the lighting device is adapted to be inserted into an existing recessed can light in a ceiling such that the Edison type plug may be inserted into an Edison-type socket in the can light.

40. The lighting device of claim 39, wherein the lighting device is mounted in one of a wall or a ceiling and wherein a distal surface of the heat exchanger is up to about 102 mm (4 in) away from a proximal surface of the wall or the ceiling.

17

41. The lighting device of claim **39**, wherein the lighting device produces a beam that can be rotated about a vertical axis and a horizontal axis, and wherein a top surface of the heat exchanger is up to about 65 mm (2.6 in) away from a proximal surface of the wall or the ceiling.

5

42. The lighting device of claim **33**, wherein the lighting device is used for new construction, wherein the lighting device is mounted in one of a wall or a ceiling, and wherein a top surface of the heat exchanger is up to about 137 mm (5.4 in) away from a proximal surface of the wall or the ceiling.

10

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18